

# TPS70345-EP

## DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS

SGLS323A – JANUARY 2006 – REVISED MARCH 2006

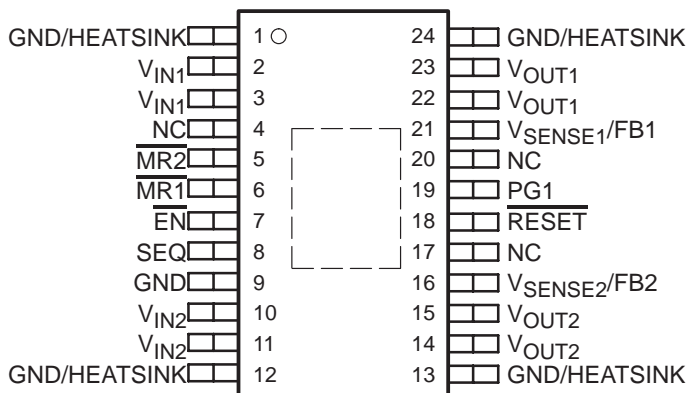
- **Controlled Baseline**
  - One Assembly/Test Site, One Fabrication Site
- **Extended Temperature Performance of –55°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree†**
- **Dual Output Voltages for Split-Supply Applications**
- **Selectable Power Up Sequencing for DSP Applications (See TPS704xx for Independent Enabling of Each Output)**
- **Output Current Range of 1 A on Regulator 1 and 2 A on Regulator 2**
- **Fast Transient Response**
- **Output Voltages of 3.3–V/1.2–V**
- **Open Drain Power-On Reset With 120-ms Delay**
- **Open Drain Power Good for Regulator 1**
- **Ultralow 185 μA (typ) Quiescent Current**
- **2 μA Input Current During Standby**
- **Low Noise: 78 μV<sub>RMS</sub> Without Bypass Capacitor**
- **Quick Output Capacitor Discharge Feature**
- **Two Manual Reset Inputs**
- **2% Accuracy Over Load and Temperature**
- **Undervoltage Lockout (UVLO) Feature**
- **24-Pin PowerPAD™ TSSOP Package**
- **Thermal Shutdown Protection**

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

### description

The TPS70345 is designed to provide a complete power management solution for Texas Instruments DSP, processor power, ASIC, FPGA, and digital applications where dual output voltage regulators are required. Easy programmability of the sequencing function makes this family ideal for any Texas Instruments DSP applications with power sequencing requirement. Differentiated features, such as accuracy, fast transient response, SVS supervisory circuit (power on reset), manual reset inputs, and enable function, provide a complete system solution.

**PWP PACKAGE  
(TOP VIEW)**



NC – No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PowerPAD is a trademark of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



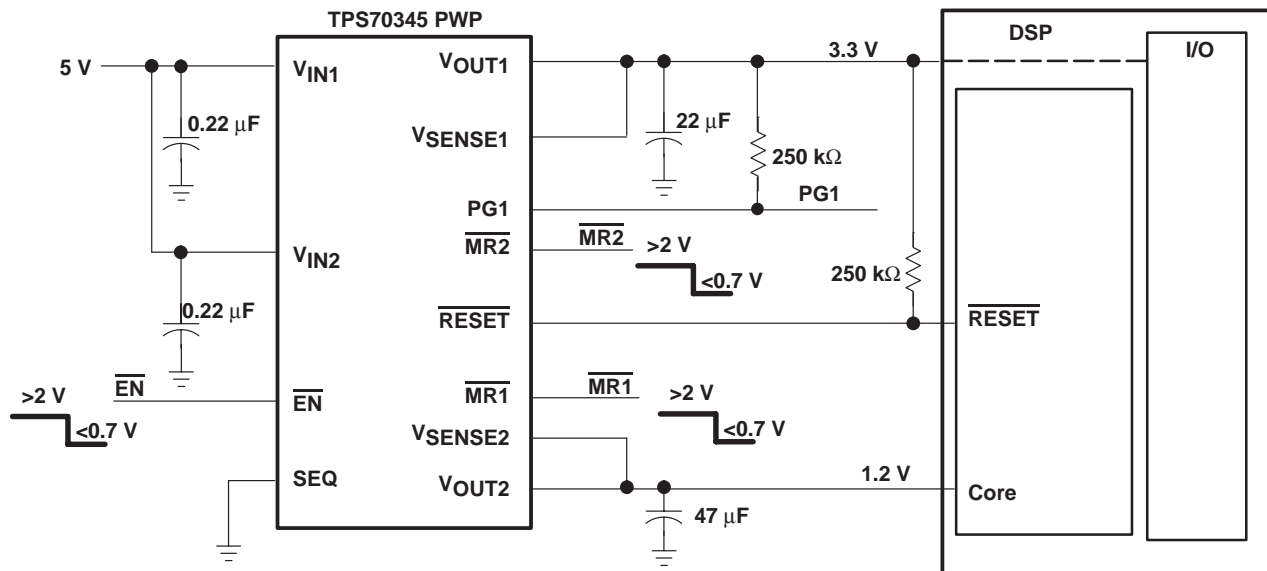
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2006, Texas Instruments Incorporated

# TPS70345-EP DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS

SGLS323A – JANUARY 2006 – REVISED MARCH 2006

## description (continued)



The TPS70345 voltage regulator offers low dropout voltage and dual outputs with power up sequence control, which is designed primarily for DSP applications. This device has a low noise output performance without using any added filter bypass capacitors and are designed to have a fast transient response and be stable with 47 µF low ESR capacitors.

This device has a fixed output voltage 3.3 V/1.2 V. Regulator 1 can support up to 1 A, and regulator 2 can support up to 2 A. Separate voltage inputs allow the designer to configure the source power.

Because the PMOS pass element behaves as a low-value resistor, the dropout voltage is very low (typically 160 mV on regulator 1) and is directly proportional to the output current. Additionally, since the PMOS pass element is a voltage-driven device, the quiescent current is low and independent of output loading (maximum of 250 µA over the full range of output current). This LDO family also features a sleep mode; applying a high signal to  $\overline{EN}$  (enable) shuts down both regulators, reducing the input current to 1 µA at  $T_J = 25^\circ\text{C}$ .

The device is enabled when the  $\overline{EN}$  pin is connected to a low-level input voltage. The output voltages of the two regulators are sensed at the  $V_{SENSE1}$  and  $V_{SENSE2}$  pins respectively.

The input signal at the SEQ pin controls the power-up sequence of the two regulators. When the device is enabled and the SEQ terminal is pulled high or left open,  $V_{OUT2}$  turns on first and  $V_{OUT1}$  remains off until  $V_{OUT2}$  reaches approximately 83% of its regulated output voltage. At that time  $V_{OUT1}$  is turned on. If  $V_{OUT2}$  is pulled below 83% (i.e. overload condition) of its regulated voltage,  $V_{OUT1}$  will be turned off. Pulling the SEQ terminal low reverses the power-up order and  $V_{OUT1}$  is turned on first. The SEQ pin is connected to an internal pullup current source.

For each regulator, there is an internal discharge transistor to discharge the output capacitor when the regulator is turned off (disabled).

The PG1 pin reports the voltage conditions at  $V_{OUT1}$ . The PG1 pin can be used to implement a SVS (power on reset) for the circuitry supplied by regulator 1.

# TPS70345-EP

## DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS

SGLS323A – JANUARY 2006 – REVISED MARCH 2006

### description (continued)

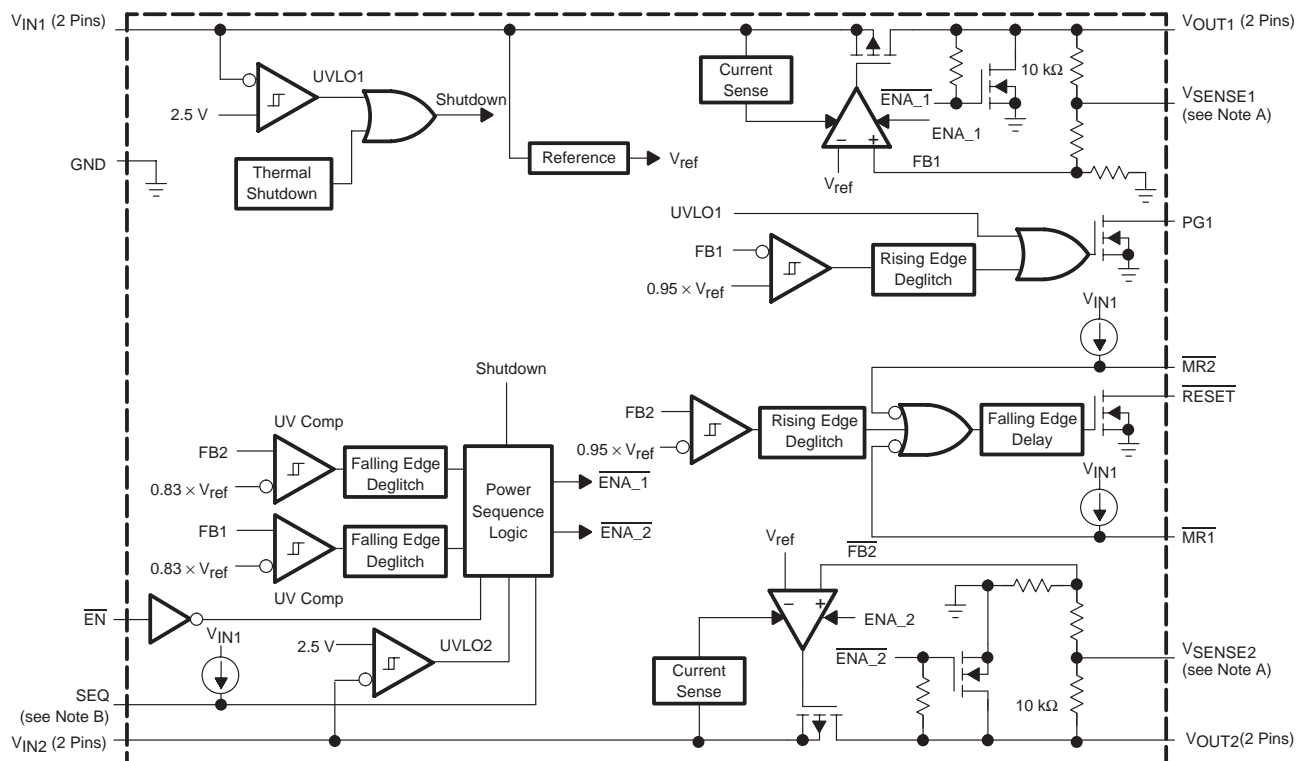
The TPS70345 features a  $\overline{\text{RESET}}$  (SVS, POR, or power on reset).  $\overline{\text{RESET}}$  is an active low, open drain output and requires a pullup resistor for normal operation. When pulled up,  $\overline{\text{RESET}}$  goes to a high impedance state (i.e. logic high) after a 120 ms delay when all three of the following conditions are met. First,  $V_{\text{IN}1}$  must be above the undervoltage condition. Second, the manual reset ( $\overline{\text{MR}}$ ) pin must be in a high impedance state. Third,  $V_{\text{OUT}2}$  must be above approximately 95% of its regulated voltage. To monitor  $V_{\text{OUT}1}$ , the PG1 output pin can be connected to  $\overline{\text{MR}1}$  or  $\overline{\text{MR}2}$ .  $\overline{\text{RESET}}$  can be used to drive power on reset or a low-battery indicator. If  $\overline{\text{RESET}}$  is not used, it can be left floating.

Internal bias voltages are powered by  $V_{\text{IN}1}$  and require 2.7 V for full functionality. Each regulator input has an undervoltage lockout circuit that prevents each output from turning on until the respective input reaches 2.5 V.

### AVAILABLE OPTIONS

$T_J$	REGULATOR 1 $V_O$ (V)	REGULATOR 2 $V_O$ (V)	TSSOP (PWP)
-55°C to 125°C	3.3 V	1.2 V	TPS70345MPWPREP

### detailed block diagram – fixed voltage version

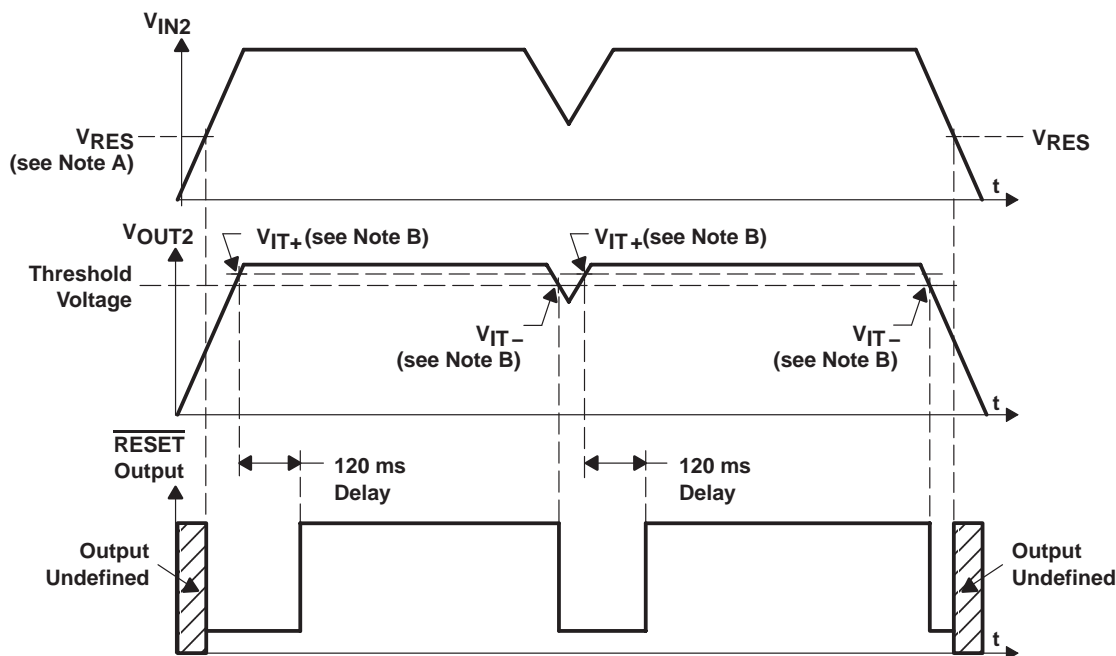


- NOTES: A. For most applications,  $V_{\text{SENSE}1}$  and  $V_{\text{SENSE}2}$  should be externally connected to  $V_{\text{OUT}}$  as close as possible to the device. For other implementations, refer to SENSE terminal connection discussion in the Application Information section.
- B. If the SEQ terminal is floating at the input,  $V_{\text{OUT}2}$  powers up first.

# TPS70345-EP DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS

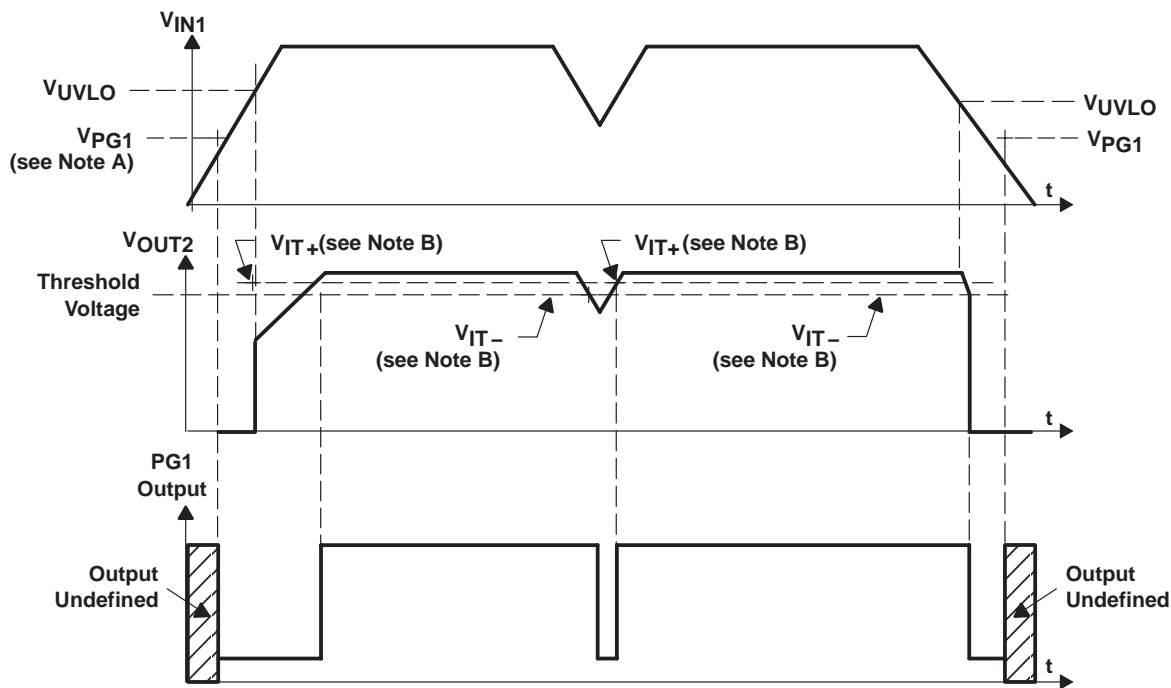
SGLS323A – JANUARY 2006 – REVISED MARCH 2006

## RESET timing diagram (with $V_{IN1}$ powered up and $\overline{MR1}$ and $\overline{MR2}$ at logic high)



- NOTES: A.  $V_{RES}$  is the minimum input voltage for a valid  $\overline{RESET}$ . The symbol  $V_{RES}$  is not currently listed within EIA or JEDEC standards for semiconductor symbology.  
B.  $V_{IT-}$  – Trip voltage is typically 5% lower than the output voltage ( $95\%V_O$ )  $V_{IT-}$  to  $V_{IT+}$  is the hysteresis voltage.

## PG1 timing diagram



- NOTES: A.  $V_{PG}$  is the minimum input voltage for a valid PG. The symbol  $V_{PG}$  is not currently listed within EIA or JEDEC standards for semiconductor symbology.  
B.  $V_{IT-}$  – Trip voltage is typically 5% lower than the output voltage ( $95\%V_O$ )  $V_{IT-}$  to  $V_{IT+}$  is the hysteresis voltage.



**TPS70345-EP**

**DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS  
WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS**

SGLS323A – JANUARY 2006 – REVISED MARCH 2006

**Terminal Functions**

TERMINAL NAME	NO.	I/O	DESCRIPTION
EN	7	I	Active low enable
GND	9		Regulator ground
GND/HEATSINK	1, 12, 13, 24		Ground/heatsink
MR1	6	I	Manual reset input 1, active low, pulled up internally
MR2	5	I	Manual reset input 2, active low, pulled up internally
NC	4, 17, 20		No connection
PG1	19	O	Open drain output, low when $V_{OUT1}$ voltage is less than 95% of the nominal regulated voltage
RESET	18	O	Open drain output, SVS (power on reset) signal, active low
SEQ	8	I	Power up sequence control: SEQ=High, $V_{OUT2}$ powers up first; SEQ=Low, $V_{OUT1}$ powers up first, SEQ terminal pulled up internally.
$V_{IN1}$	2, 3	I	Input voltage of regulator 1
$V_{IN2}$	10, 11	I	Input voltage of regulator 2
$V_{OUT1}$	22, 23	O	Output voltage of regulator 1
$V_{OUT2}$	14, 15	O	Output voltage of regulator 2
$V_{SENSE2}$	16	I	Regulator 2 output voltage sense
$V_{SENSE1}$	21	I	Regulator 1 output voltage sense

**detailed description**

The TPS70345 low dropout regulator provides dual regulated output voltages for DSP applications that require a high performance power management solution. These devices provide fast transient response and high accuracy, while drawing low quiescent current. Programmable sequencing provides a power solution for DSPs without any external component requirements. This reduces the component cost and board space while increasing total system reliability. The TPS70345 has an enable feature which puts the device in sleep mode reducing the input current to 1  $\mu$ A. Other features are the integrated SVS (power on reset,  $\overline{\text{RESET}}$ ) and power good (PG1). These monitor output voltages and provide logic output to the system. These differentiated features provide a complete DSP power solution.

The TPS70345, unlike many other LDOs, features low quiescent current which remains virtually constant even with varying loads. Conventional LDO regulators use a PNP pass element, the base current of which is directly proportional to the load current through the regulator ( $I_B = I_C/\beta$ ). The TPS70345 uses a PMOS transistor to pass current. Because the gate of the PMOS is voltage driven, operating current is low and stable over the full load range.

**pin functions**

**enable**

The  $\overline{\text{EN}}$  terminal is an input which enables or shuts down the device. If  $\overline{\text{EN}}$  is at a logic high signal the device is in shutdown mode. When the  $\overline{\text{EN}}$  goes to voltage low, then the device is enabled.

**sequence**

The SEQ terminal is an input that programs which output voltage ( $V_{OUT1}$  or  $V_{OUT2}$ ) is turned on first. When the device is enabled and the SEQ terminal is pulled high or left open,  $V_{OUT2}$  turns on first and  $V_{OUT1}$  remains off until  $V_{OUT2}$  reaches approximately 83% of its regulated output voltage. If  $V_{OUT2}$  is pulled below 83% (i.e., over load condition)  $V_{OUT1}$  is turned off. This terminal has a 6- $\mu$ A pullup current to  $V_{IN1}$ .

Pulling the SEQ terminal low reverses the power-up order and  $V_{OUT1}$  is turned on first. For detailed timing diagrams see Figure 26 through Figure 30.



# TPS70345-EP

## DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS

SGLS323A – JANUARY 2006 – REVISED MARCH 2006

---

### detailed description (continued)

#### *power good (PG1)*

The PG1 terminal is an open drain, active high output terminal which indicates the status of the  $V_{OUT1}$  regulator. When the  $V_{OUT1}$  reaches 95% of its regulated voltage, PG1 goes to a high impedance state. PG1 goes to a low impedance state when  $V_{OUT1}$  is pulled below 95% (i.e., over load condition) of its regulated voltage. The open drain output of the PG1 terminal requires a pullup resistor.

#### *manual reset pins ( $\overline{MR1}$ and $\overline{MR2}$ )*

$\overline{MR1}$  and  $\overline{MR2}$  are active low input terminals used to trigger a reset condition. When either  $\overline{MR1}$  or  $\overline{MR2}$  is pulled to logic low, a POR ( $\overline{RESET}$ ) occurs. These terminals have a 6- $\mu$ A pullup current to  $V_{IN1}$ . It is recommended that these pins be pulled high to  $V_{IN}$  when they are not used.

#### *sense ( $V_{SENSE1}$ , $V_{SENSE2}$ )*

The sense terminals of fixed-output options must be connected to the regulator output, and the connection should be as short as possible. Internally, the sense terminals connect to high-impedance wide-bandwidth amplifiers through resistor-divider networks and noise pickup feeds through to the regulator output. It is essential to route the sense connections in such a way to minimize/avoid noise pickup. Adding RC networks between the  $V_{SENSE}$  terminals and  $V_{OUT}$  terminals to filter noise is not recommended because it can cause the regulators to oscillate.

#### *$\overline{RESET}$ indicator*

$\overline{RESET}$  is an active low, open drain output and requires a pullup resistor for normal operation. When pulled up,  $\overline{RESET}$  goes to a high impedance state (i.e. logic high) after a 120 ms delay when all three of the following conditions are met. First,  $V_{IN1}$  must be above the undervoltage condition. Second, the manual reset ( $\overline{MR}$ ) pin must be in a high impedance state. Third,  $V_{OUT2}$  must be above approximately 95% of its regulated voltage. To monitor  $V_{OUT1}$ , the PG1 output pin can be connected to  $\overline{MR1}$  or  $\overline{MR2}$ .

#### *$V_{IN1}$ and $V_{IN2}$*

$V_{IN1}$  and  $V_{IN2}$  are inputs to the regulators.

#### *$V_{OUT1}$ and $V_{OUT2}$*

$V_{OUT1}$  and  $V_{OUT2}$  are output terminals of each regulator.



**TPS70345-EP**  
**DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS**  
**WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS**

SGLS323A – JANUARY 2006 – REVISED MARCH 2006

**absolute maximum ratings over operating junction temperature (unless otherwise noted)†**

Input voltage range‡: $V_{IN1}$ .....	-0.3 V to 7 V
$V_{IN2}$ .....	-0.3 V to 7 V
Voltage range at $\overline{EN}$ .....	-0.3 V to 7 V
Output voltage range ( $V_{OUT1}$ , $V_{SENSE1}$ ) .....	5.5 V
Output voltage range ( $V_{OUT2}$ , $V_{SENSE2}$ ) .....	5.5 V
Maximum $\overline{RESET}$ , PG1 voltage .....	7 V
Maximum $\overline{MR1}$ , $\overline{MR2}$ , and SEQ voltage .....	$V_{IN1}$
Peak output current .....	Internally limited
Operating virtual junction temperature range, $T_J$ .....	-55°C to 150°C
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C
ESD rating, HBM .....	2 kV

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

‡ All voltages are tied to network ground.

**recommended operating conditions**

	MIN	MAX	UNIT
Input voltage, $V_I$ ¶	2.7	6	V
Output current, $I_O$ (regulator 1)	0	1	A
Output current, $I_O$ (regulator 2)	0	2	A
Operating virtual junction temperature, $T_J$	-55	125	°C

¶ To calculate the minimum input voltage for maximum output current, use the following equation:  $V_{I(min)} = V_{O(max)} + V_{DO(max\ load)}$ .



# TPS70345-EP

## DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS

### WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS

SGLS323A – JANUARY 2006 – REVISED MARCH 2006

electrical characteristics over recommended operating junction temperature ( $T_J = -55^\circ\text{C}$  to  $125^\circ\text{C}$ )  
 $V_{IN1}$  or  $V_{IN2} = V_{OUTX(nom)} + 1\text{ V}$ ,  $I_{OUTX} = 1\text{ mA}$ ,  $EN = 0$ ,  $C_{OUT1} = 22\ \mu\text{F}$ ,  $C_{OUT2} = 47\ \mu\text{F}$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_O$	Output voltage (see Note 1 and Note 3)	Reference voltage $2.7\text{ V} < V_I < 6\text{ V}$ , FB connected to $V_O$ $T_J = 25^\circ\text{C}$		1.224		V
		$2.7\text{ V} < V_I < 6\text{ V}$ , FB connected to $V_O$	1.196		1.248	
	1.2 V Output ( $V_{OUT2}$ )	$2.7\text{ V} < V_I < 6\text{ V}$ , $T_J = 25^\circ\text{C}$		1.2		
		$2.7\text{ V} < V_I < 6\text{ V}$	1.176		1.224	
Quiescent current (GND current) for regulator 1 and regulator 2, $EN = 0\text{ V}$ , (see Note 1)		See Note 3, $T_J = 25^\circ\text{C}$		185		$\mu\text{A}$
		See Note 3			250	
Output voltage line regulation ( $\Delta V_O/V_O$ ) for regulator 1 and regulator 2 (see Note 2)		$V_O + 1\text{ V} < V_I \leq 6\text{ V}$ , $T_J = 25^\circ\text{C}$ , See Note 1		0.01%		V
		$V_O + 1\text{ V} < V_I \leq 6\text{ V}$ , See Note 1			0.1%	
Load regulation for $V_{OUT1}$ and $V_{OUT2}$		$T_J = 25^\circ\text{C}$ , See Note 3		1		mV
Output current limit	Regulator 1	$V_O = 0\text{ V}$		1.75	2.35	A
	Regulator 2			3.8	4.8	
Thermal shutdown junction temperature				150		$^\circ\text{C}$
$I_{I(standby)}$	Standby current	$EN = V_I$ , $T_J = 25^\circ\text{C}$		1	2	$\mu\text{A}$
		$EN = V_I$			10	
<b>RESET terminal</b>						
Minimum input voltage for valid $\overline{\text{RESET}}$		$I(\overline{\text{RESET}}) = 300\ \mu\text{A}$ , $V(\overline{\text{RESET}}) \leq 0.8\text{ V}$		1	1.3	V
Trip threshold voltage		$V_O$ decreasing	92%	95%	98%	$V_O$
Hysteresis voltage		Measured at $V_O$		0.5%		$V_O$
$t(\overline{\text{RESET}})$		$\overline{\text{RESET}}$ pulse duration	80	120	160	ms
$t_r(\overline{\text{RESET}})$		Rising edge deglitch		30		$\mu\text{s}$
Output low voltage		$V_I = 3.5\text{ V}$ , $I(\overline{\text{RESET}}) = 1\text{ mA}$		0.15	0.4	V
Leakage current		$V(\overline{\text{RESET}}) = 6\text{ V}$			1	$\mu\text{A}$
<b>PG terminal</b>						
Minimum input voltage for valid PG		$I(\text{PG}) = 300\ \mu\text{A}$ , $V(\text{PG}_1) \leq 0.8\text{ V}$		1.0	1.3	V
Trip threshold voltage		$V_O$ decreasing	92%	95%	98%	$V_O$
Hysteresis voltage		Measured at $V_O$		0.5%		$V_O$
$t_r(\text{PG}_1)$		Rising edge deglitch		30		$\mu\text{s}$
Output low voltage		$V_I = 2.7\text{ V}$ , $I(\text{PG}) = 1\text{ mA}$		0.15	0.4	V
Leakage current		$V(\text{PG}_1) = 6\text{ V}$			1	$\mu\text{A}$
<b>EN terminal</b>						
High-level $EN$ input voltage				2		V
Low-level $EN$ input voltage					0.7	V
Input current ( $EN$ )			-1		1	$\mu\text{A}$

NOTES: 1. Minimum input operating voltage is  $2.7\text{ V}$  or  $V_{O(\text{typ})} + 1\text{ V}$ , whichever is greater. Maximum input voltage =  $6\text{ V}$ , minimum output current is  $1\text{ mA}$ .

2. If  $V_O < 1.8\text{ V}$  then  $V_{I\text{max}} = 6\text{ V}$ ,  $V_{I\text{min}} = 2.7\text{ V}$ :

$$\text{Line regulation (mV)} = (\%/V) \times \frac{V_O(V_{I\text{max}} - 2.7\text{ V})}{100} \times 1000$$

If  $V_O > 2.5\text{ V}$  then  $V_{I\text{max}} = 6\text{ V}$ ,  $V_{I\text{min}} = V_O + 1\text{ V}$ :

$$\text{Line regulation (mV)} = (\%/V) \times \frac{V_O(V_{I\text{max}} - (V_O + 1))}{100} \times 1000$$

3.  $I_O = 1\text{ mA}$  to  $1\text{ A}$  for regulator 1 and  $1\text{ mA}$  to  $2\text{ A}$  for regulator 2.





**TPS70345-EP**  
**DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS**  
**WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS**

SGLS323A – JANUARY 2006 – REVISED MARCH 2006

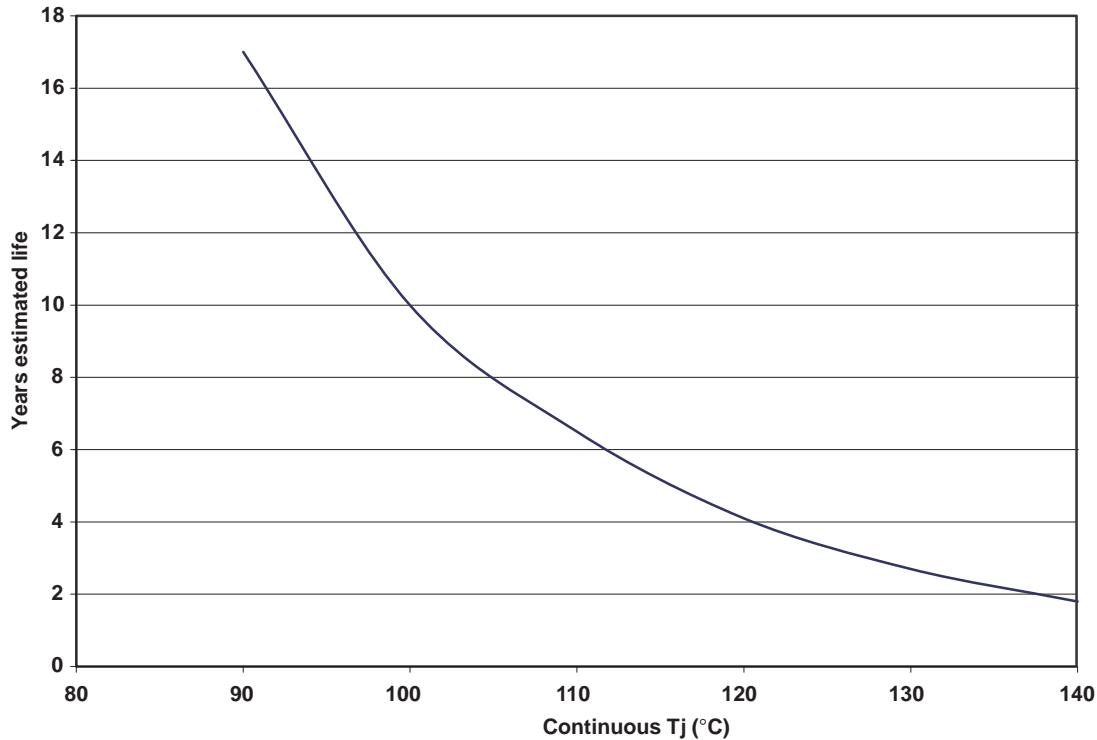
electrical characteristics over recommended operating junction temperature ( $T_J = -55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ )  
 $V_{IN1}$  or  $V_{IN2} = V_{OUTX(nom)} + 1\text{ V}$ ,  $I_{OUTX} = 1\text{ mA}$ ,  $EN = 0$ ,  $C_{OUT1} = 22\text{ }\mu\text{F}$ ,  $C_{OUT2} = 47\text{ }\mu\text{F}$  (unless otherwise noted) (continued)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>SEQ TERMINAL</b>					
High-level SEQ input voltage		2			V
Low-level SEQ input voltage				0.7	V
SEQ pullup current source			6		$\mu\text{A}$
<b>MR1 / MR2 TERMINALS</b>					
High-level input voltage		2			V
Low-level input voltage				0.7	V
Pullup current source			9.5		$\mu\text{A}$
<b>V<sub>OUT2</sub> TERMINAL</b>					
V <sub>OUT2</sub> UV comparator – positive-going input threshold voltage of V <sub>OUT1</sub> UV comparator		80% V <sub>O</sub>	83% V <sub>O</sub>	86% V <sub>O</sub>	V
V <sub>OUT2</sub> UV comparator – hysteresis			3% V <sub>O</sub>		mV
V <sub>OUT2</sub> UV comparator – falling edge deglitch	V <sub>SENSE2</sub> decreasing below threshold		140		$\mu\text{s}$
Peak output current	2 ms pulse width		3		A
Discharge transistor current	V <sub>OUT2</sub> = 1.5 V		7.5		mA
<b>V<sub>OUT1</sub> TERMINAL</b>					
V <sub>OUT1</sub> UV comparator – positive-going input threshold voltage of V <sub>OUT1</sub> UV comparator		80% V <sub>O</sub>	83% V <sub>O</sub>	86% V <sub>O</sub>	V
V <sub>OUT1</sub> UV comparator – hysteresis			3% V <sub>O</sub>		mV
V <sub>OUT1</sub> UV comparator – falling edge deglitch	V <sub>SENSE1</sub> decreasing below threshold		140		$\mu\text{s}$
Dropout voltage (see Note 4)	I <sub>O</sub> = 1 A, V <sub>IN1</sub> = 3.2 V, T <sub>J</sub> = 25°C		160		mV
	I <sub>O</sub> = 1 A, V <sub>IN1</sub> = 3.2 V			255	
Peak output current	2 ms pulse width		1.2		A
Discharge transistor current	V <sub>OUT1</sub> = 1.5 V		7.5		mA
<b>V<sub>IN1</sub> / V<sub>IN2</sub> TERMINAL</b>					
UVLO threshold		2.3		2.65	V
UVLO hysteresis			110		mV

NOTE 4: Input voltage ( $V_{IN1}$  or  $V_{IN2}$ ) =  $V_O(\text{Typ}) - 100\text{ mV}$ . For the 1.5-V, 1.8-V and 2.5-V regulators, the dropout voltage is limited by input voltage range. The 3.3 V regulator input voltage is set to 3.2 V to perform this test.

**TPS70345-EP**  
**DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS**  
**WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS**

SGLS323A – JANUARY 2006 – REVISED MARCH 2006



**Figure 1. TPS70345-PWP-EP Estimated Device Life at Elevated Temperature Wirebond Voiding Fail Modes**

**TYPICAL CHARACTERISTICS**

**Table of Graphs**

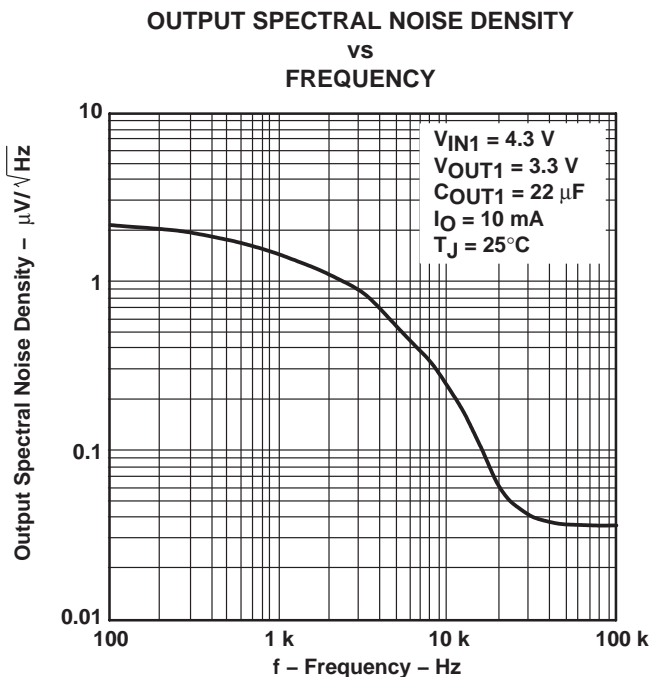
			<b>FIGURE</b>
	Output spectral noise density	vs Frequency	2 – 5
$z_o$	Output impedance	vs Frequency	6 – 9
	Load transient response		10, 11
	Line transient response		12, 13
$V_O$	Output voltage and enable voltage	vs Time (start-up)	14, 15
	Equivalent series resistance	vs Output current	16 – 20



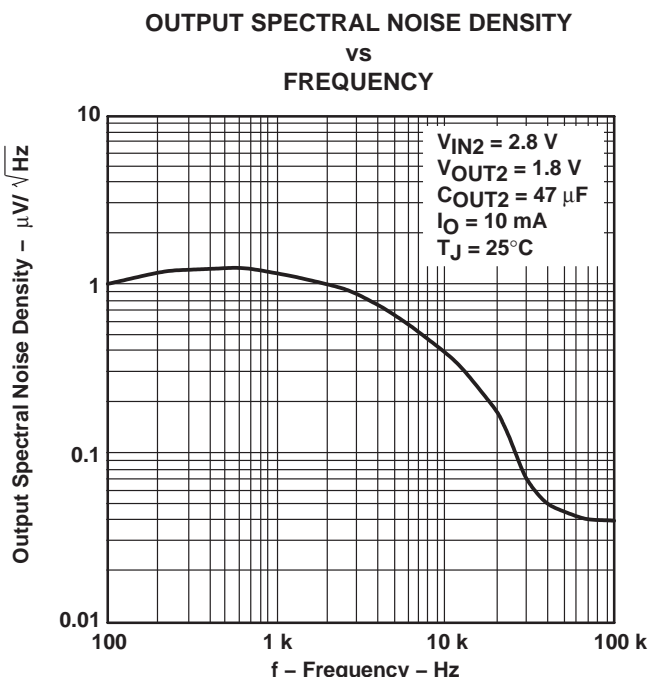
**TPS70345-EP**  
**DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS**  
**WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS**

SGLS323A – JANUARY 2006 – REVISED MARCH 2006

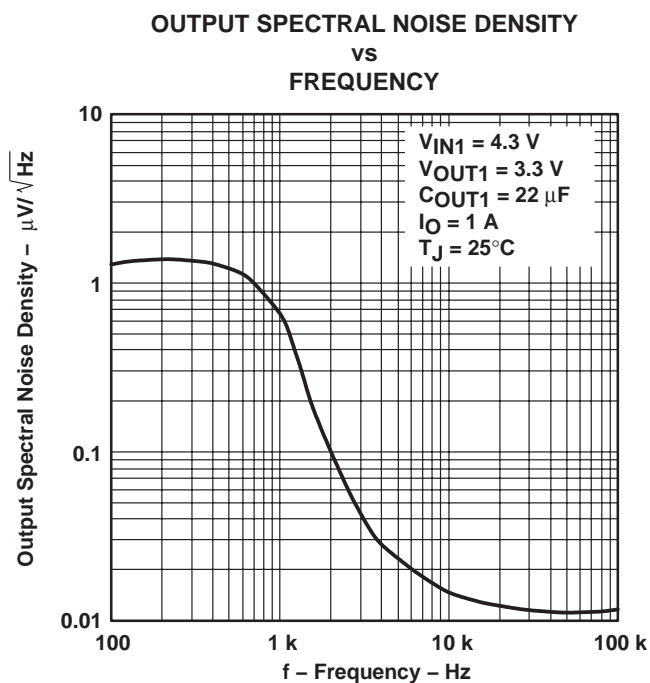
**TYPICAL CHARACTERISTICS**



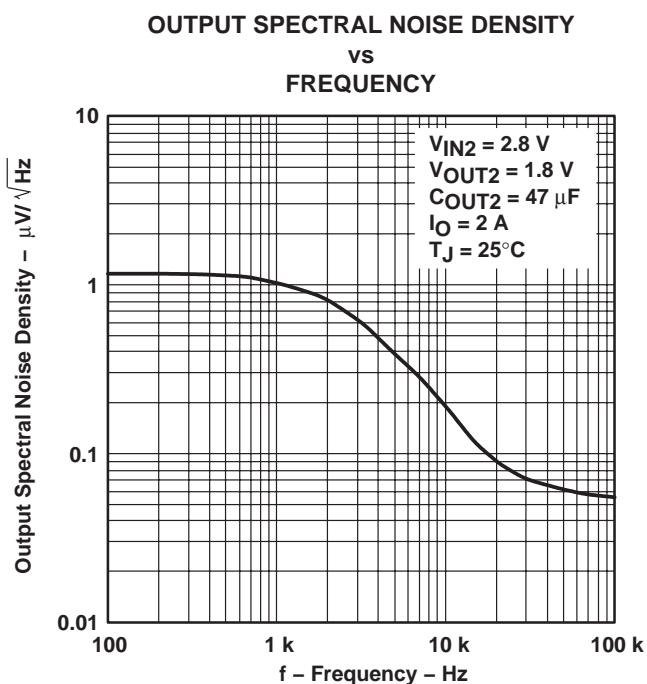
**Figure 2**



**Figure 3**



**Figure 4**



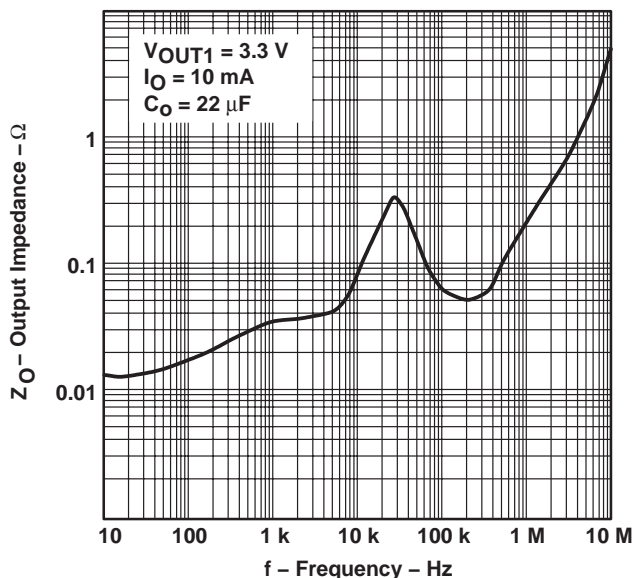
**Figure 5**

**TPS70345-EP**  
**DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS**  
**WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS**

SGLS323A – JANUARY 2006 – REVISED MARCH 2006

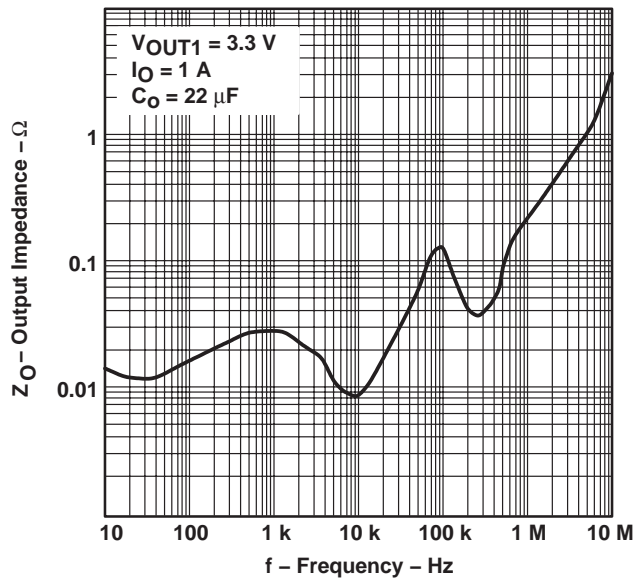
**TYPICAL CHARACTERISTICS**

**OUTPUT IMPEDANCE  
 vs  
 FREQUENCY**



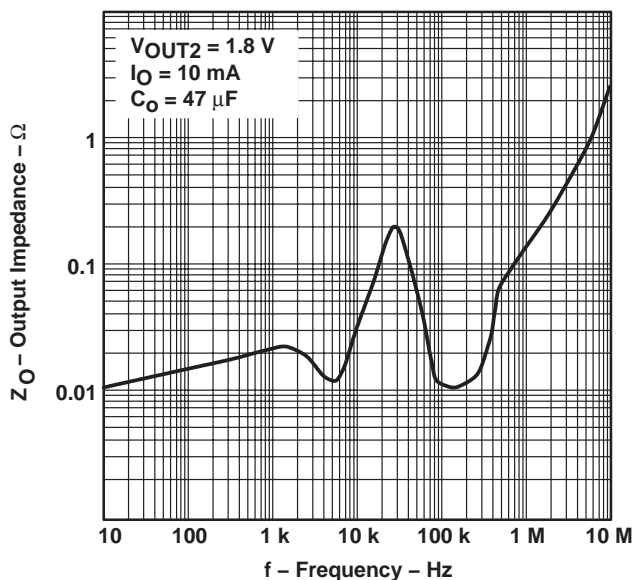
**Figure 6**

**OUTPUT IMPEDANCE  
 vs  
 FREQUENCY**



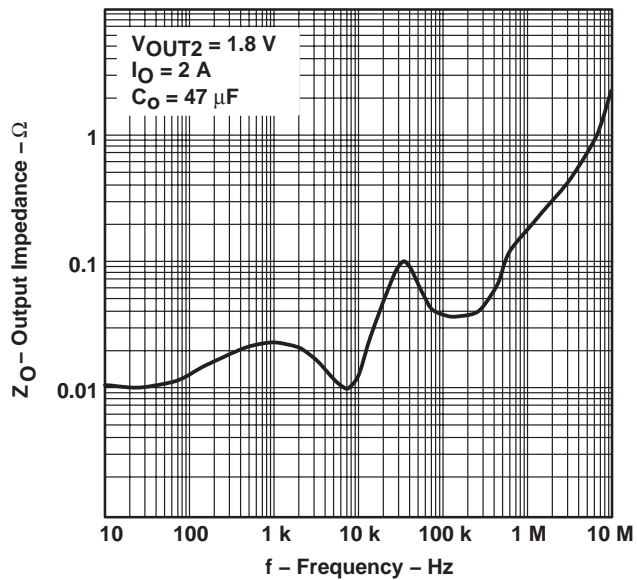
**Figure 7**

**OUTPUT IMPEDANCE  
 vs  
 FREQUENCY**



**Figure 8**

**OUTPUT IMPEDANCE  
 vs  
 FREQUENCY**



**Figure 9**

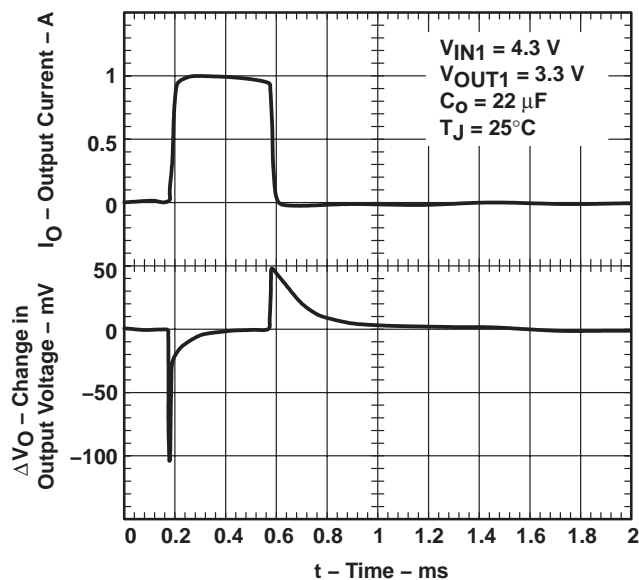


**TPS70345-EP**  
**DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS**  
**WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS**

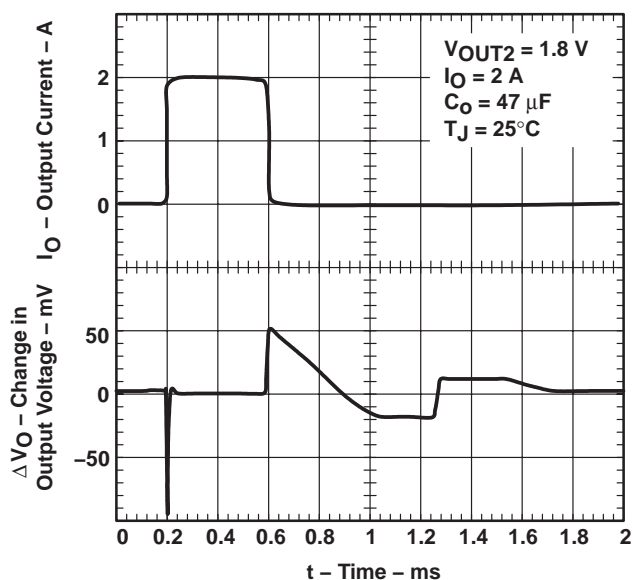
SGLS323A – JANUARY 2006 – REVISED MARCH 2006

**TYPICAL CHARACTERISTICS**

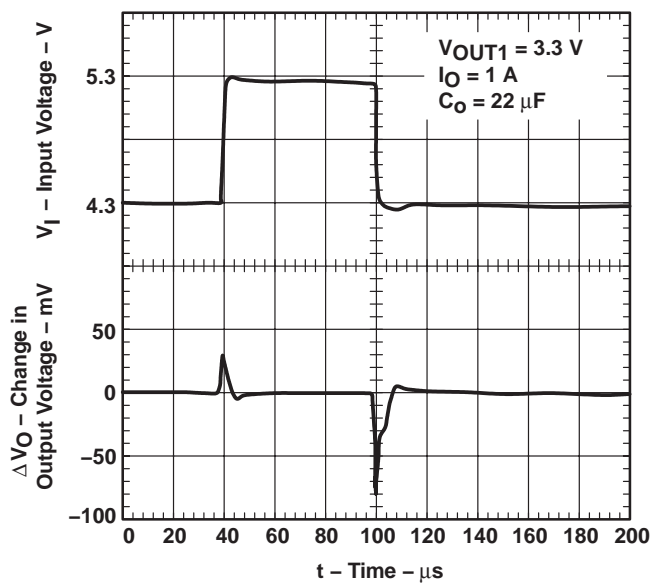
**LOAD TRANSIENT RESPONSE**



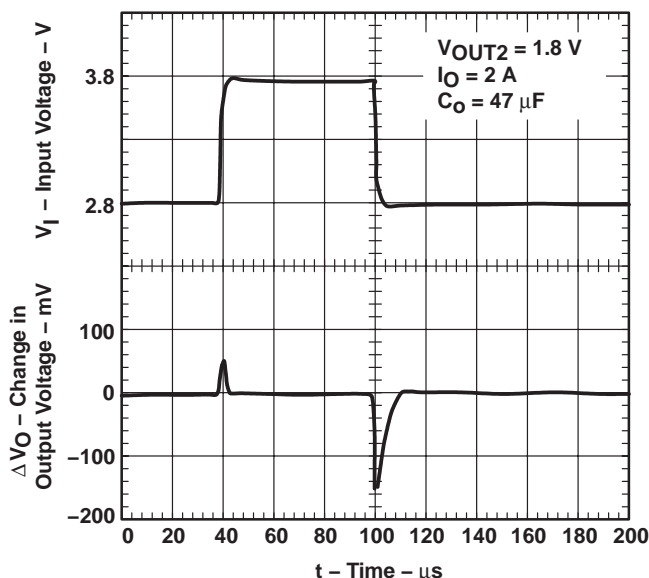
**LOAD TRANSIENT RESPONSE**



**LINE TRANSIENT RESPONSE**



**LINE TRANSIENT RESPONSE**

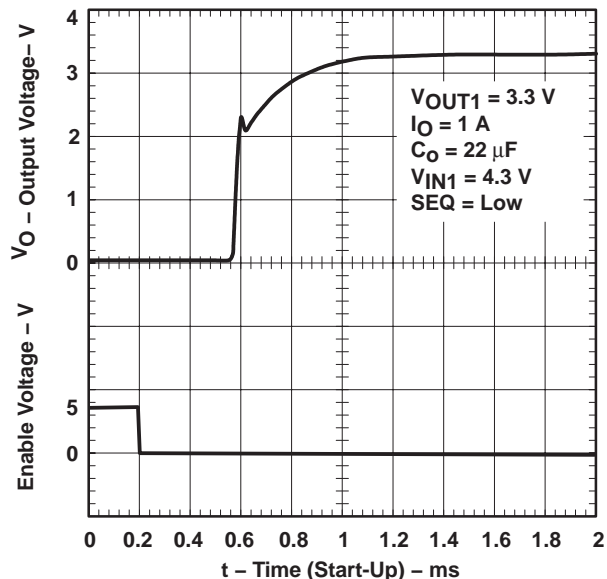


**TPS70345-EP**  
**DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS**  
**WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS**

SGLS323A – JANUARY 2006 – REVISED MARCH 2006

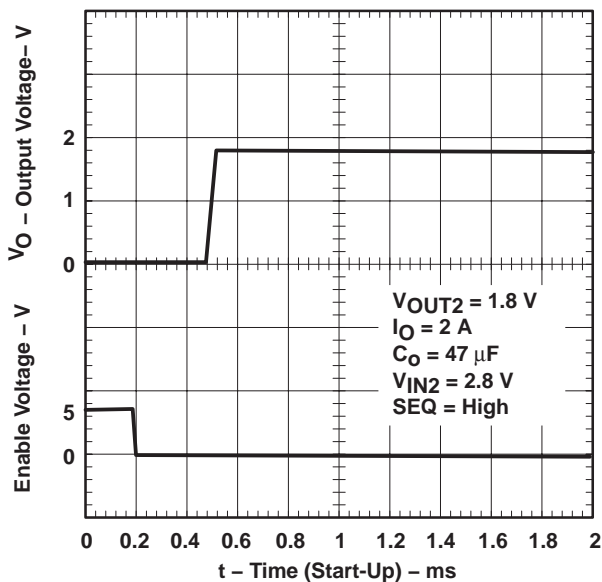
**TYPICAL CHARACTERISTICS**

**OUTPUT VOLTAGE AND ENABLE VOLTAGE  
 vs  
 TIME (START-UP)**

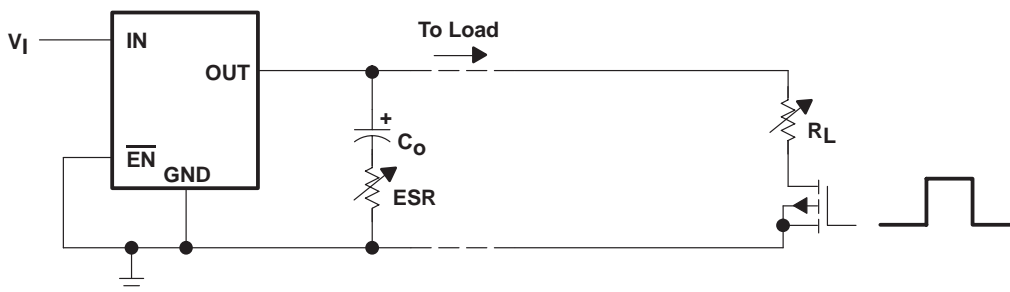


**Figure 14**

**OUTPUT VOLTAGE AND ENABLE VOLTAGE  
 vs  
 TIME (START-UP)**



**Figure 15**



**Figure 16. Test Circuit for Typical Regions of Stability**

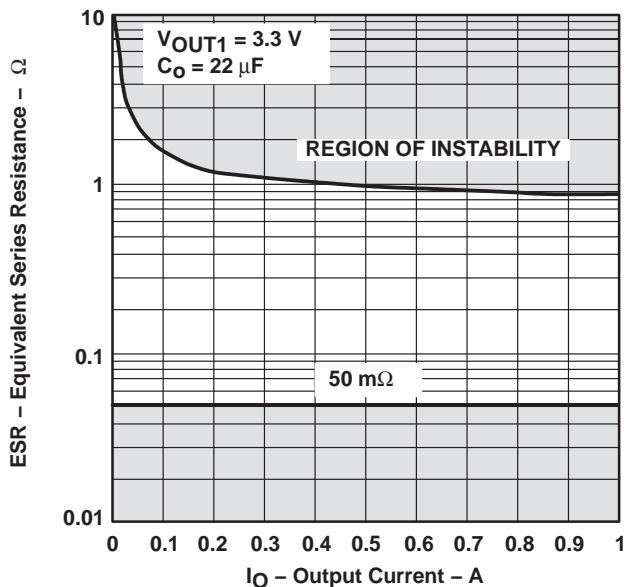
† Equivalent series resistance (ESR) refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to  $C_O$ .

**TPS70345-EP**  
**DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS**  
**WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS**

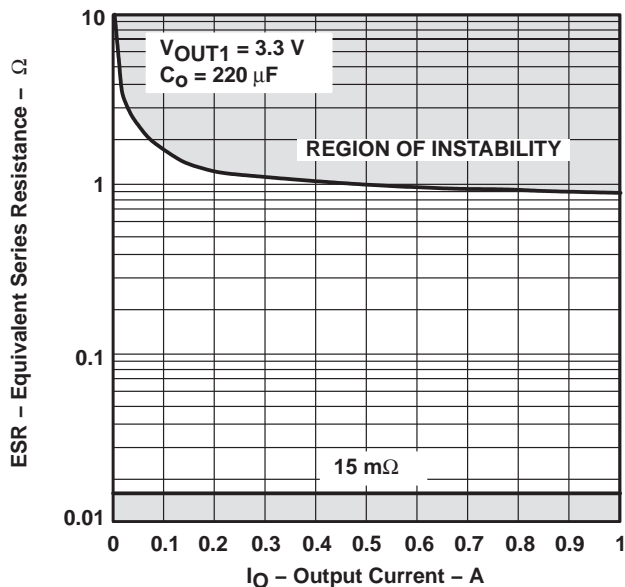
SGLS323A – JANUARY 2006 – REVISED MARCH 2006

**TYPICAL CHARACTERISTICS**

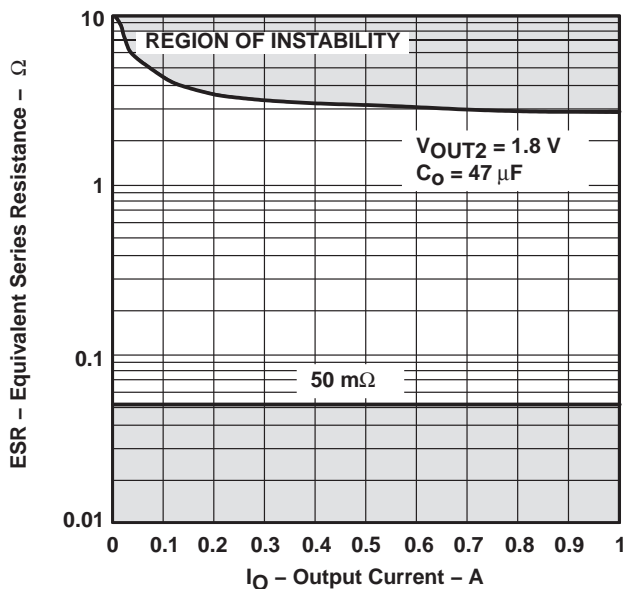
**TYPICAL REGION OF STABILITY  
EQUIVALENT SERIES RESISTANCE (ESR)<sup>†</sup>  
vs  
OUTPUT CURRENT**



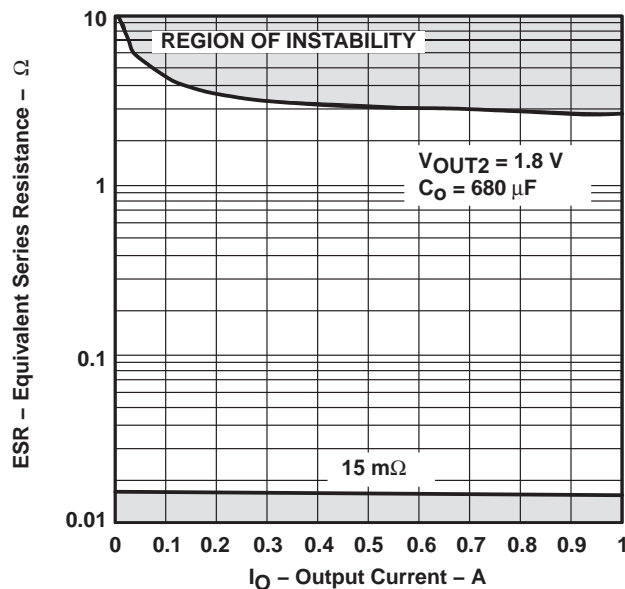
**TYPICAL REGION OF STABILITY  
EQUIVALENT SERIES RESISTANCE (ESR)<sup>†</sup>  
vs  
OUTPUT CURRENT**



**TYPICAL REGION OF STABILITY  
EQUIVALENT SERIES RESISTANCE (ESR)<sup>†</sup>  
vs  
OUTPUT CURRENT**



**TYPICAL REGION OF STABILITY  
EQUIVALENT SERIES RESISTANCE (ESR)<sup>†</sup>  
vs  
OUTPUT CURRENT**



<sup>†</sup> Equivalent series resistance (ESR) refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to  $C_O$ .

# TPS70345-EP DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS

SGLS323A – JANUARY 2006 – REVISED MARCH 2006

## THERMAL INFORMATION

### thermally enhanced TSSOP-24 (PWP – PowerPad™)

The thermally enhanced PWP package is based on the 24-pin TSSOP, but includes a thermal pad (see Figure 21(c)) to provide an effective thermal contact between the IC and the PWB.

Traditionally, surface mount and power have been mutually exclusive terms. A variety of scaled-down TO220-type packages have leads formed as gull wings to make them applicable for surface-mount applications. These packages, however, suffer from several shortcomings: they do not address the low profile requirements (<2 mm) of many of today's advanced systems, and they do not offer a pin-count high enough to accommodate increasing integration. On the other hand, traditional low-power surface-mount packages require power-dissipation derating that severely limits the usable range of many high-performance analog circuits.

The PWP package (thermally enhanced TSSOP) combines fine-pitch surface-mount technology with thermal performance comparable to much larger power packages.

The PWP package is designed to optimize the heat transfer to the PWB. Because of the small size and limited mass of a TSSOP package, thermal enhancement is achieved by improving the thermal conduction paths that remove heat from the component. The thermal pad is formed using a lead-frame design (patent pending) and manufacturing technique to provide the user with direct connection to the heat-generating IC. When this pad is soldered or otherwise coupled to an external heat dissipator, high power dissipation in the ultrathin, fine-pitch, surface-mount package can be reliably achieved.

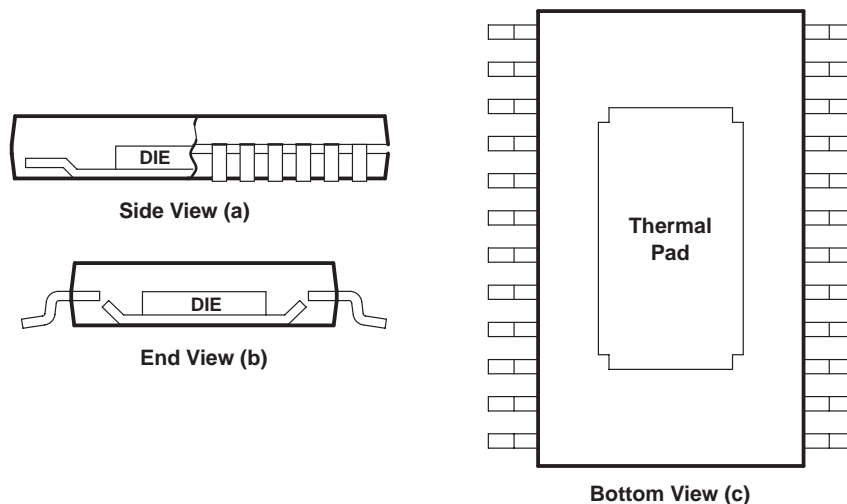


Figure 21. Views of Thermally Enhanced PWP Package

Because the conduction path has been enhanced, power-dissipation capability is determined by the thermal considerations in the PWB design. For example, simply adding a localized copper plane (heat-sink surface), which is coupled to the thermal pad, enables the PWP package to dissipate 2.5 W in free air (reference Figure 23(a), 8 cm<sup>2</sup> of copper heat sink and natural convection). Increasing the heat-sink size increases the power dissipation range for the component. The power dissipation limit can be further improved by adding airflow to a PWB/IC assembly (see Figure 22 and Figure 23). The line drawn at 0.3 cm<sup>2</sup> in Figure 22 and Figure 23 indicates performance at the minimum recommended heat-sink size, illustrated in Figure 24.



**THERMAL INFORMATION**

**thermally enhanced TSSOP-24 (PWP – PowerPad™) (continued)**

The thermal pad is directly connected to the substrate of the IC, which for the TPS70345 series is a secondary electrical connection to device ground. The heat-sink surface that is added to the PWP can be a ground plane or left electrically isolated. In TO220-type surface-mount packages, the thermal connection is also the primary electrical connection for a given terminal which is not always ground. The PWP package provides up to 24 independent leads that can be used as inputs and outputs (Note: leads 1, 12, 13, and 24 are internally connected to the thermal pad and the IC substrate).

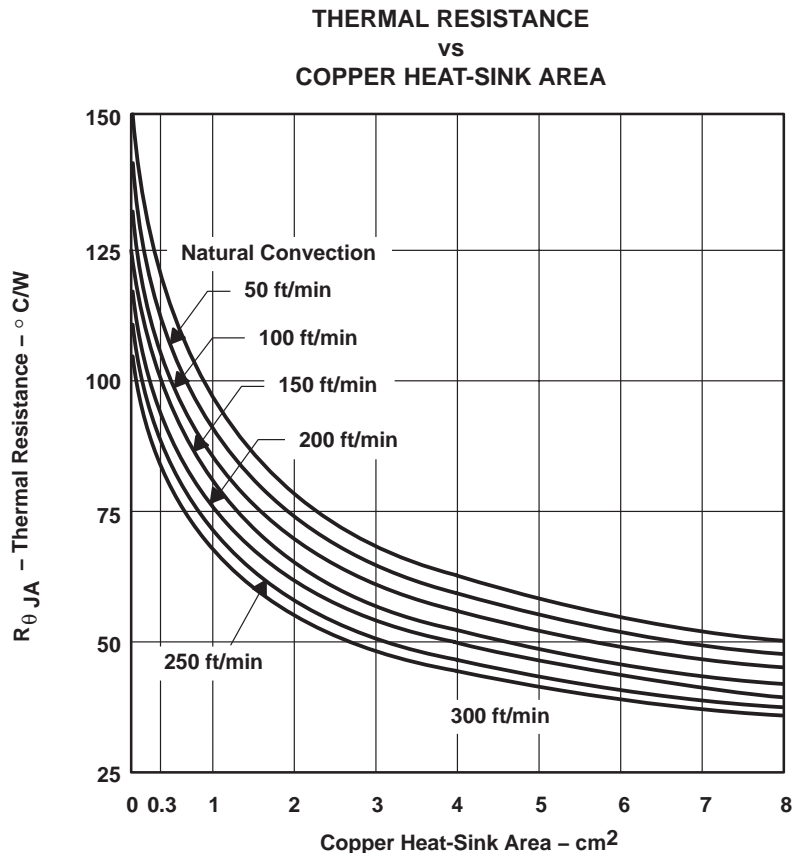


Figure 22

**TPS70345-EP**  
**DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS**  
**WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS**

SGLS323A – JANUARY 2006 – REVISED MARCH 2006

**THERMAL INFORMATION**

thermally enhanced TSSOP-24 (PWP – PowerPad™) (continued)

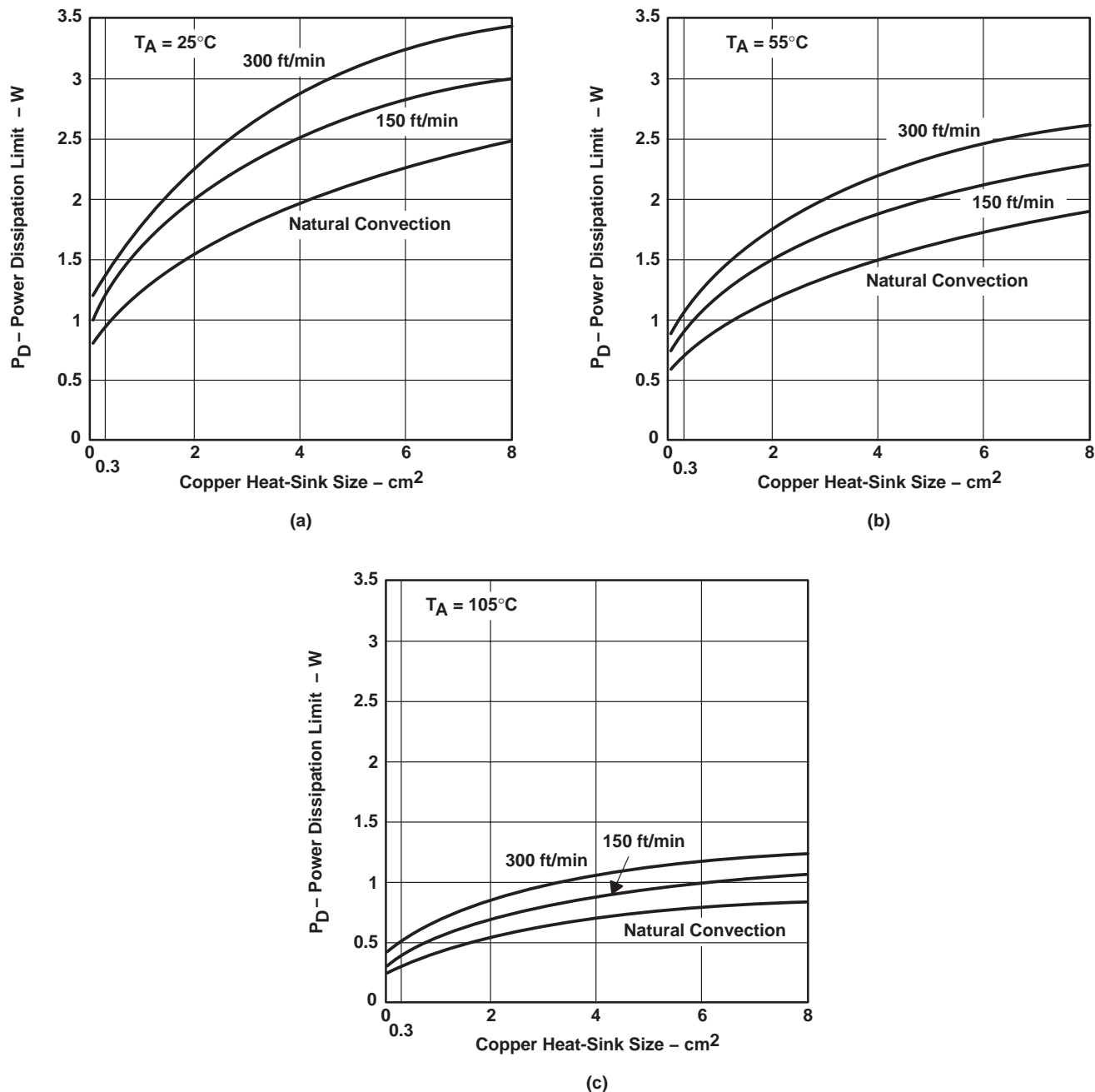
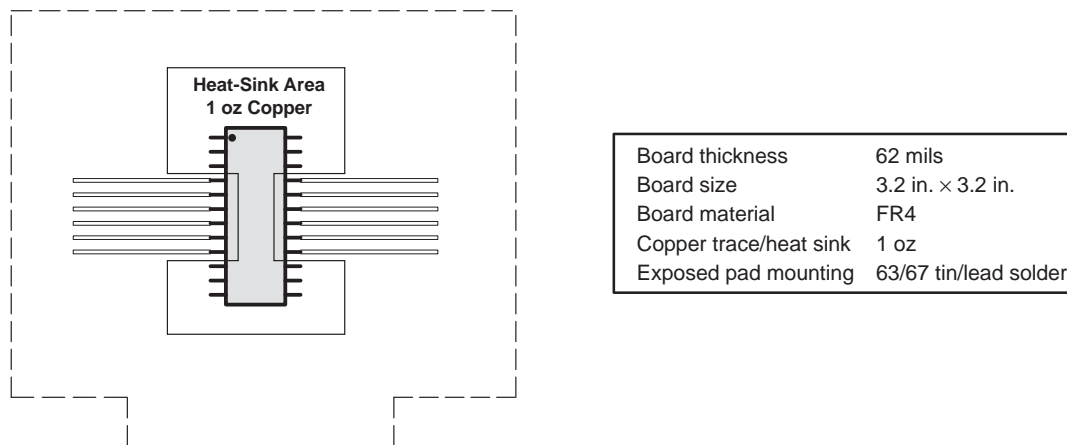


Figure 23. Power Ratings of the PWP Package at Ambient Temperatures of 25°C, 55°C, and 105°C

## THERMAL INFORMATION

### thermally enhanced TSSOP-24 (PWP – PowerPad™) (continued)

Figure 24 is an example of a thermally enhanced PWB layout for use with the new PWP package. This board configuration was used in the thermal experiments that generated the power ratings shown in Figure 22 and Figure 23. As discussed earlier, copper has been added on the PWB to conduct heat away from the device.  $R_{\theta JA}$  for this assembly is illustrated in Figure 22 as a function of heat-sink area. A family of curves is included to illustrate the effect of airflow introduced into the system.



**Figure 24. PWB Layout (Including Copper Heatsink Area) for Thermally Enhanced PWP Package**

From Figure 22,  $R_{\theta JA}$  for a PWB assembly can be determined and used to calculate the maximum power-dissipation limit for the component/PWB assembly, with the equation:

$$P_{D(max)} = \frac{T_{Jmax} - T_A}{R_{\theta JA(system)}} \quad (1)$$

where

$T_{Jmax}$  is the maximum specified junction temperature (150°C absolute maximum limit, 125°C recommended operating limit) and  $T_A$  is the ambient temperature.

$P_{D(max)}$  should then be applied to the internal power dissipated by the TPS70345 regulator. The equation for calculating total internal power dissipation of the TPS70345 is:

$$P_{D(total)} = (V_{IN1} - V_{OUT1}) \times I_{OUT1} + V_{IN1} \times \frac{I_Q}{2} + (V_{IN2} - V_{OUT2}) \times I_{OUT2} + V_{IN2} \times \frac{I_Q}{2} \quad (2)$$

Since the quiescent current of the TPS703xx is low, the second term is negligible, further simplifying the equation to:

$$P_{D(total)} = (V_{IN1} - V_{OUT1}) \times I_{OUT1} + (V_{IN2} - V_{OUT2}) \times I_{OUT2} \quad (3)$$

For the case where  $T_A = 55^\circ\text{C}$ , airflow = 200 ft/min, copper heat-sink area = 4 cm<sup>2</sup>, the maximum power-dissipation limit can be calculated. First, from Figure 22, we find the system  $R_{\theta JA}$  is 50°C/W; therefore, the maximum power-dissipation limit is:

$$P_{D(max)} = \frac{T_{Jmax} - T_A}{R_{\theta JA(system)}} = \frac{125^\circ\text{C} - 55^\circ\text{C}}{\text{TBD } ^\circ\text{C/W}} = \text{TBD W} \quad (4)$$

**TPS70345-EP**  
**DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS**  
**WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS**

SGLS323A – JANUARY 2006 – REVISED MARCH 2006

**THERMAL INFORMATION**

**thermally enhanced TSSOP-24 (PWP – PowerPad™) (continued)**

If the system implements a TPS70345 regulator, where  $V_I = 5\text{ V}$  and  $I_O = 800\text{ mA}$ , the internal power dissipation is:

$$P_{D(\text{total})} = (V_{\text{IN1}} - V_{\text{OUT1}}) \times I_{\text{OUT1}} + (V_{\text{IN2}} - V_{\text{OUT2}}) \times I_{\text{OUT2}} \tag{5}$$

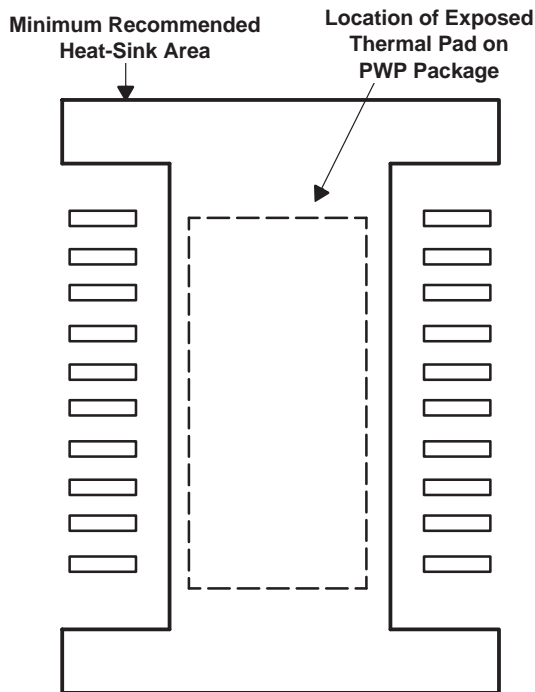
$$= (4.3 - 3.3) \times 0.8 + (2.8 - 1.8) \times 1 = 1.8\text{ W}$$

Comparing  $P_{D(\text{total})}$  with  $P_{D(\text{max})}$  reveals that the power dissipation in this example does not exceed the calculated limit. When it does, one of two corrective actions should be made: raising the power-dissipation limit by increasing the airflow or the heat-sink area, or lowering the internal power dissipation of the regulator by reducing the input voltage or the load current. In either case, the above calculations should be repeated with the new system parameters. This parameter is measured with the recommended copper heat sink pattern on a 4-layer PCB, 2 oz. copper traces on 4-in × 4-in ground layer. Simultaneous and continuous operation of both regulator outputs at full load may exceed the power dissipation rating of the PWP package.

**mounting information**

The primary requirement is to complete the thermal contact between the thermal pad and the PWB metal. The thermal pad is a solderable surface and is fully intended to be soldered at the time the component is mounted. Although voiding in the thermal-pad solder-connection is not desirable, up to 50% voiding is acceptable. The data included in Figure 22 and Figure 23 is for soldered connections with voiding between 20% and 50%. The thermal analysis shows no significant difference resulting from the variation in voiding percentage.

Figure 25 shows the solder-mask land pattern for the PWP package. The minimum recommended heat-sink area is also illustrated. This is simply a copper plane under the body extent of the package, including metal routed under terminals 1, 12, 13, and 24.



**Figure 25. PWP Package Land Pattern**

**TPS70345-EP**  
**DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS**  
**WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS**

SGLS323A – JANUARY 2006 – REVISED MARCH 2006

**APPLICATION INFORMATION**

**sequencing timing diagrams**

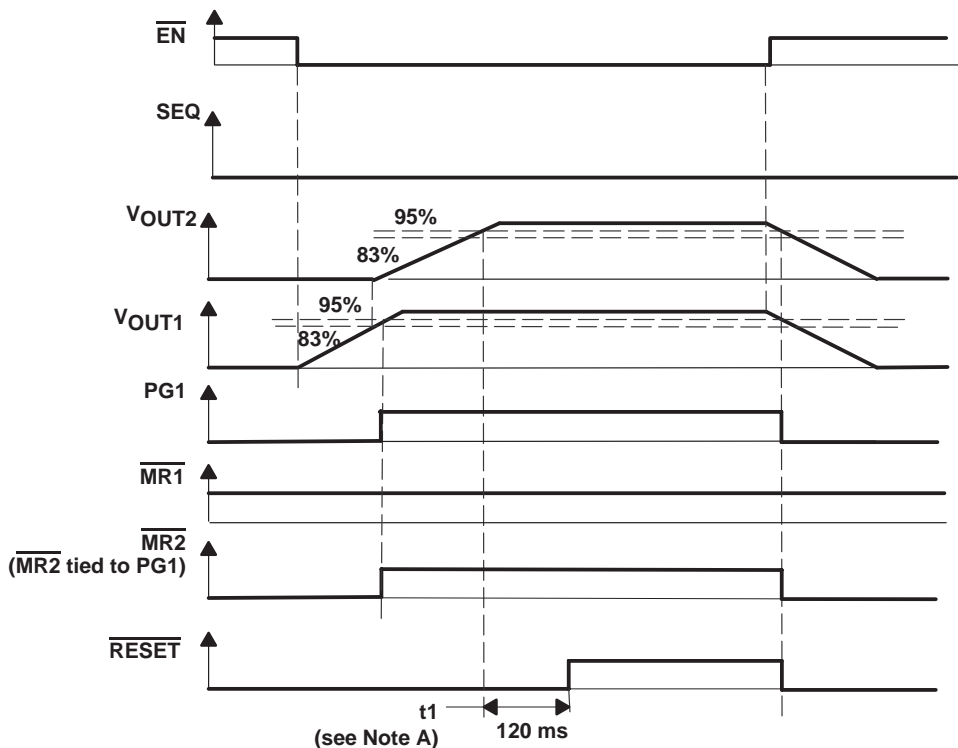
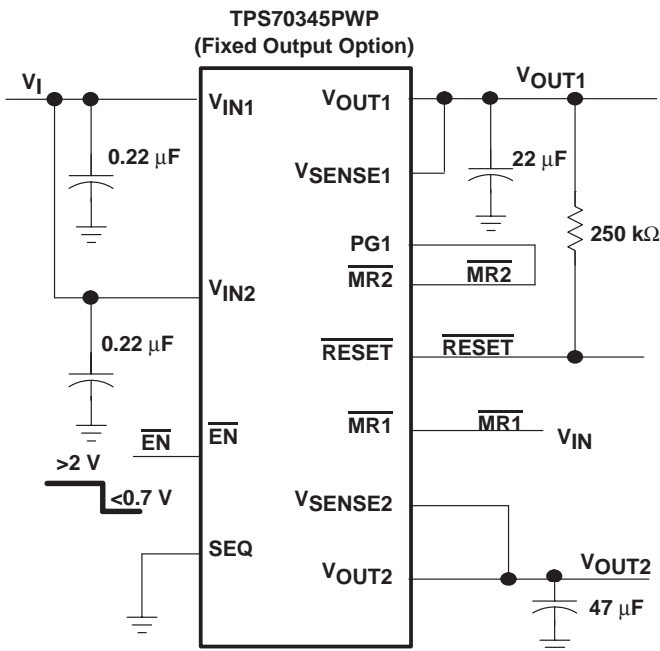
The following figures provide a timing diagram of how this device functions in different configurations.

**application conditions not shown in block diagram:**

$V_{IN1}$  and  $V_{IN2}$  are tied to the same fixed input voltage greater than the  $V_{UVLO}$ ; SEQ is tied to logic low; PG1 is tied to MR2; MR1 is not used and is connected to  $V_{IN}$ .

**explanation of timing diagrams:**

$\overline{EN}$  is initially high; therefore, both regulators are off and PG1 and RESET are at logic low. With SEQ at logic low, when  $\overline{EN}$  is taken to logic low,  $V_{OUT1}$  turns on.  $V_{OUT2}$  turns on after  $V_{OUT1}$  reaches 83% of its regulated output voltage. When  $V_{OUT1}$  reaches 95% of its regulated output voltage, PG1 (tied to  $\overline{MR2}$ ) goes to logic high. When both  $V_{OUT1}$  and  $V_{OUT2}$  reach 95% of their respective regulated output voltages and both  $\overline{MR1}$  and  $\overline{MR2}$  (tied to PG1) are at logic high, RESET is pulled to logic high after a 120 ms delay. When  $\overline{EN}$  is returned to logic high, both devices power down and both PG1 (tied to  $\overline{MR2}$ ) and RESET return to logic low.



NOTE A:  $t_1$  – Time at which both  $V_{OUT1}$  and  $V_{OUT2}$  are greater than the PG thresholds and  $\overline{MR1}$  is logic high.

**Figure 26. Timing When SEQ = Low**



# TPS70345-EP DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS

SGLS323A – JANUARY 2006 – REVISED MARCH 2006

## APPLICATION INFORMATION

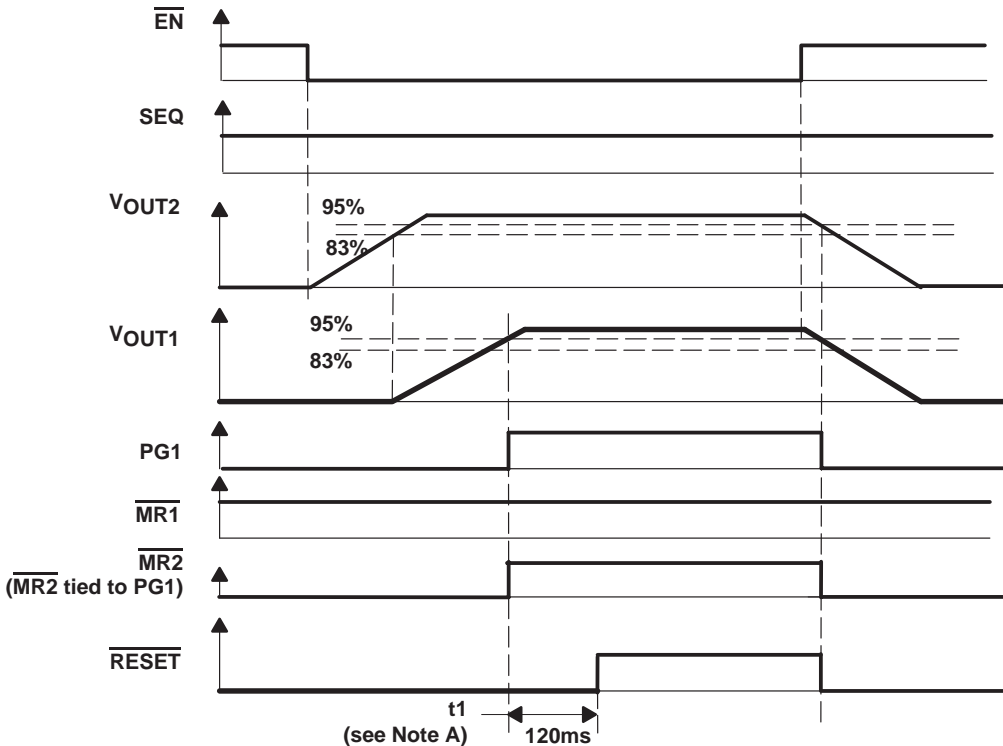
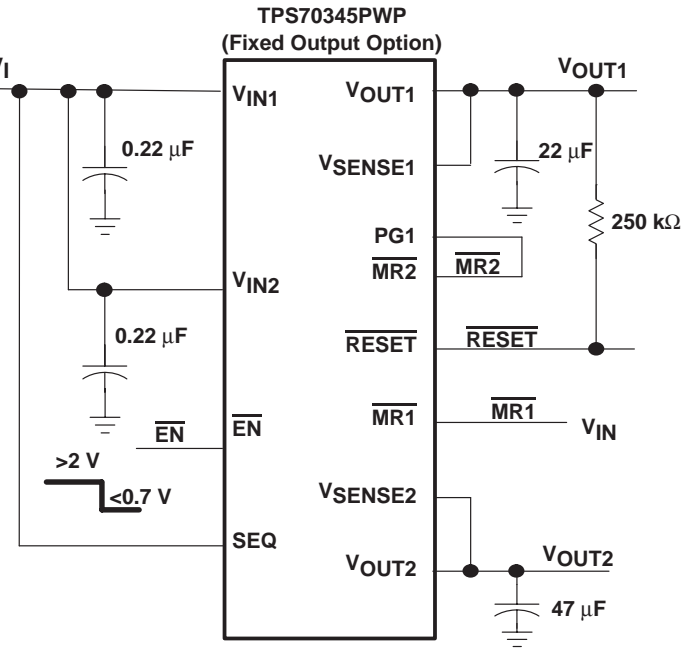
### sequencing timing diagrams (continued)

application conditions not shown in block diagram:

$V_{IN1}$  and  $V_{IN2}$  are tied to the same fixed input voltage greater than the  $V_{UVLO}$ ; SEQ is tied to logic high; PG1 is tied to MR2; MR1 is not used and is connected to  $V_{IN}$ .

### explanation of timing diagrams:

$\overline{EN}$  is initially high; therefore, both regulators are off and PG1 and RESET are at logic low. With SEQ at logic high, when  $\overline{EN}$  is taken to logic low,  $V_{OUT2}$  turns on.  $V_{OUT1}$  turns on after  $V_{OUT2}$  reaches 83% of its regulated output voltage. When  $V_{OUT1}$  reaches 95% of its regulated output voltage, PG1 (tied to MR2) goes to logic high. When both  $V_{OUT1}$  and  $V_{OUT2}$  reach 95% of their respective regulated output voltages and both MR1 and MR2 (tied to PG1) are at logic high, RESET is pulled to logic high after a 120 ms delay. When  $\overline{EN}$  is returned to logic high, both devices turn off and both PG1 (tied to MR2) and RESET return to logic low.



NOTE A:  $t_1$  – Time at which both  $V_{OUT1}$  and  $V_{OUT2}$  are greater than the PG thresholds and MR1 is logic high.

Figure 27. Timing When SEQ = High

**TPS70345-EP**  
**DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS**  
**WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS**

SGLS323A – JANUARY 2006 – REVISED MARCH 2006

**APPLICATION INFORMATION**

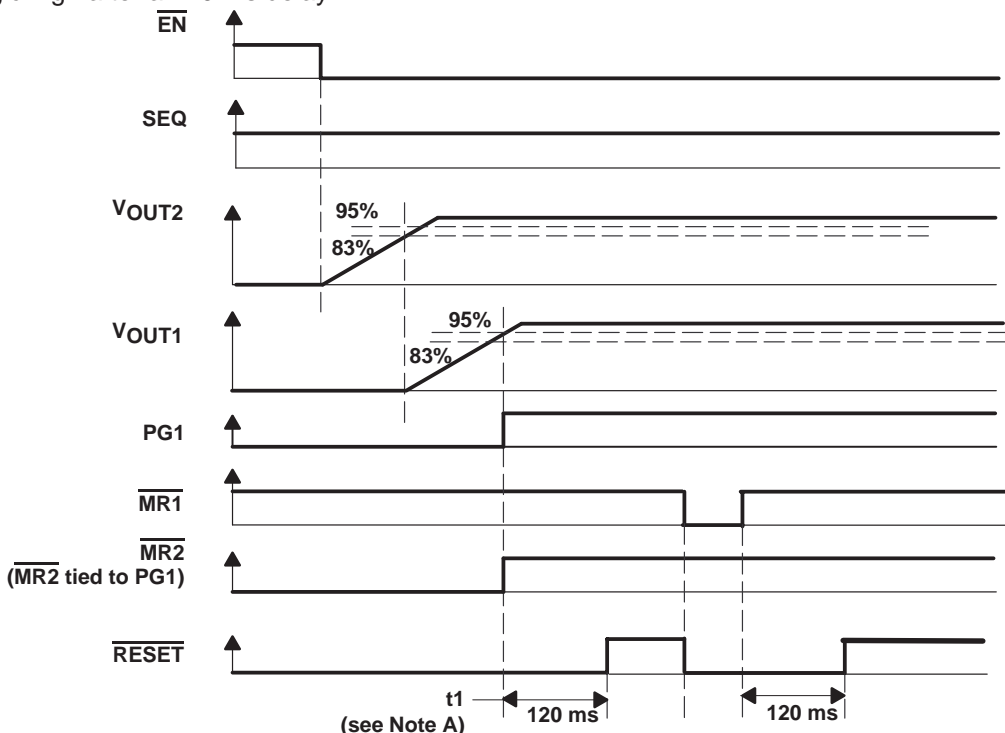
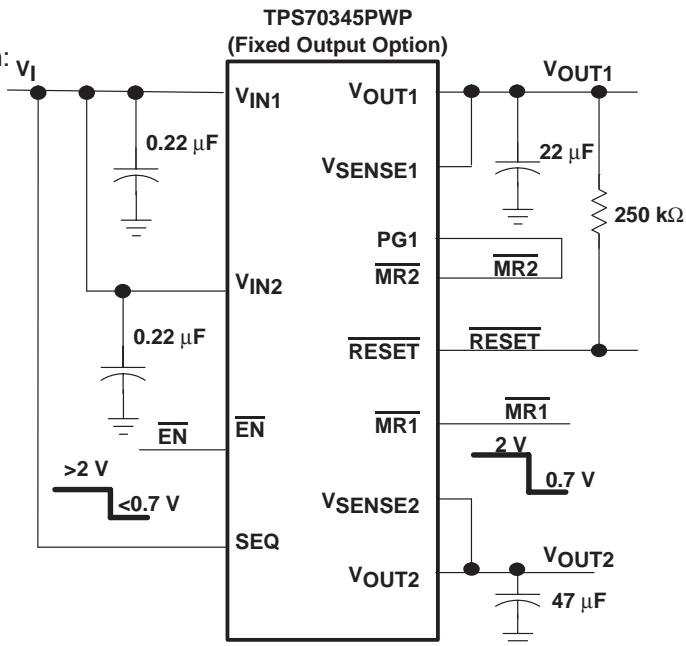
**sequencing timing diagrams (continued)**

**application conditions not shown in block diagram:**

$V_{IN1}$  and  $V_{IN2}$  are tied to the same fixed input voltage greater than the  $V_{UVLO}$ ; SEQ is tied to logic high; PG1 is tied to  $\overline{MR2}$ ;  $\overline{MR1}$  is initially at logic high but is eventually toggled.

**explanation of timing diagrams:**

$\overline{EN}$  is initially high; therefore, both regulators are off and PG1 and  $\overline{RESET}$  are at logic low. With SEQ at logic high, when  $\overline{EN}$  is taken low,  $V_{OUT2}$  turns on.  $V_{OUT1}$  turns on after  $V_{OUT2}$  reaches 83% of its regulated output voltage. When  $V_{OUT1}$  reaches 95% of its regulated output voltage, PG1 (tied to  $\overline{MR2}$ ) goes to logic high. When both  $V_{OUT1}$  and  $V_{OUT2}$  reach 95% of their respective regulated output voltages and both  $\overline{MR1}$  and  $\overline{MR2}$  (tied to PG1) are at logic high,  $\overline{RESET}$  is pulled to logic high after a 120 ms delay. When  $\overline{MR1}$  is taken low,  $\overline{RESET}$  returns to logic low but the outputs remain in regulation. When  $\overline{MR1}$  is returned to logic high, since both  $V_{OUT1}$  and  $V_{OUT2}$  remain above 95% of their respective regulated output voltages and  $\overline{MR2}$  (tied to PG1) remains at logic high,  $\overline{RESET}$  is pulled to logic high after a 120 ms delay.



NOTE A:  $t_1$  – Time at which both  $V_{OUT1}$  and  $V_{OUT2}$  are greater than the PG thresholds and  $\overline{MR1}$  is logic high.

**Figure 28. Timing When  $\overline{MR1}$  Is Toggled**

# TPS70345-EP DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS

SGLS323A – JANUARY 2006 – REVISED MARCH 2006

## APPLICATION INFORMATION

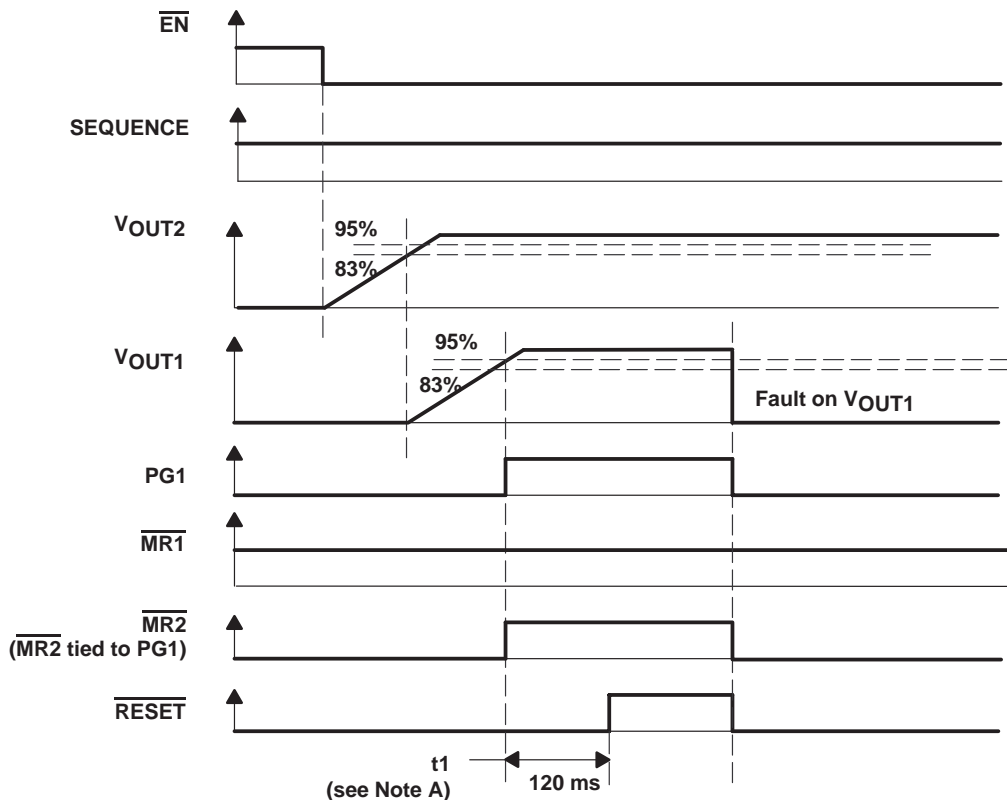
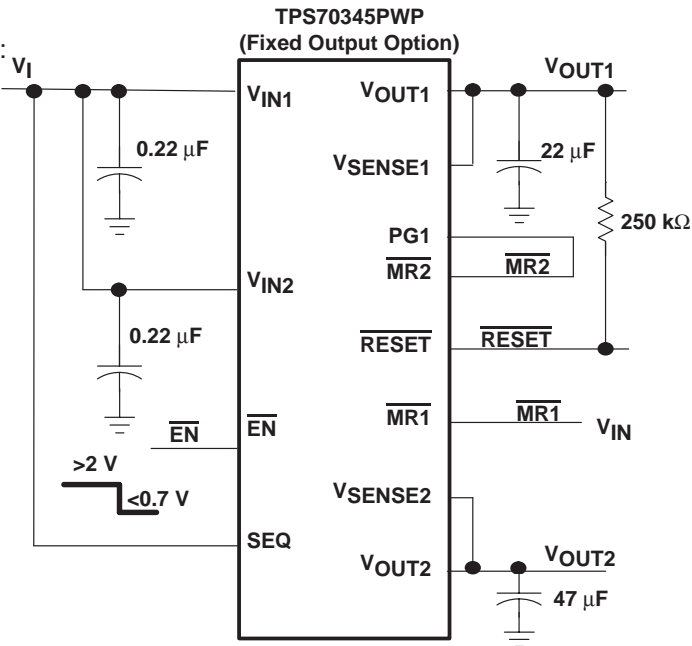
### sequencing timing diagrams (continued)

application conditions not shown in block diagram:

$V_{IN1}$  and  $V_{IN2}$  are tied to the same fixed input voltage greater than the  $V_{UVLO}$ ;  $SEQ$  is tied to logic high;  $PG1$  is tied to  $MR2$ ;  $MR1$  is not used and is connected to  $V_{IN}$ .

explanation of timing diagrams:

$\overline{EN}$  is initially high; therefore, both regulators are off and  $PG1$  and  $RESET$  are at logic low. With  $SEQ$  at logic high, when  $\overline{EN}$  is taken low,  $V_{OUT2}$  turns on.  $V_{OUT1}$  turns on after  $V_{OUT2}$  reaches 83% of its regulated output voltage. When  $V_{OUT1}$  reaches 95% of its regulated output voltage,  $PG1$  (tied to  $MR2$ ) goes to logic high. When both  $V_{OUT1}$  and  $V_{OUT2}$  reach 95% of their respective regulated output voltages and both  $MR1$  and  $MR2$  (tied to  $PG1$ ) are at logic high,  $RESET$  is pulled to logic high after a 120 ms delay. When a fault on  $V_{OUT1}$  causes it to fall below 95% of its regulated output voltage,  $PG1$  (tied to  $MR2$ ) goes to logic low.



NOTE A:  $t_1$  – Time at which both  $V_{OUT1}$  and  $V_{OUT2}$  are greater than the PG thresholds and  $\overline{MR1}$  is logic high.

Figure 29. Timing When a Fault Occurs on  $V_{OUT1}$



# TPS70345-EP

## DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS

SGLS323A – JANUARY 2006 – REVISED MARCH 2006

### APPLICATION INFORMATION

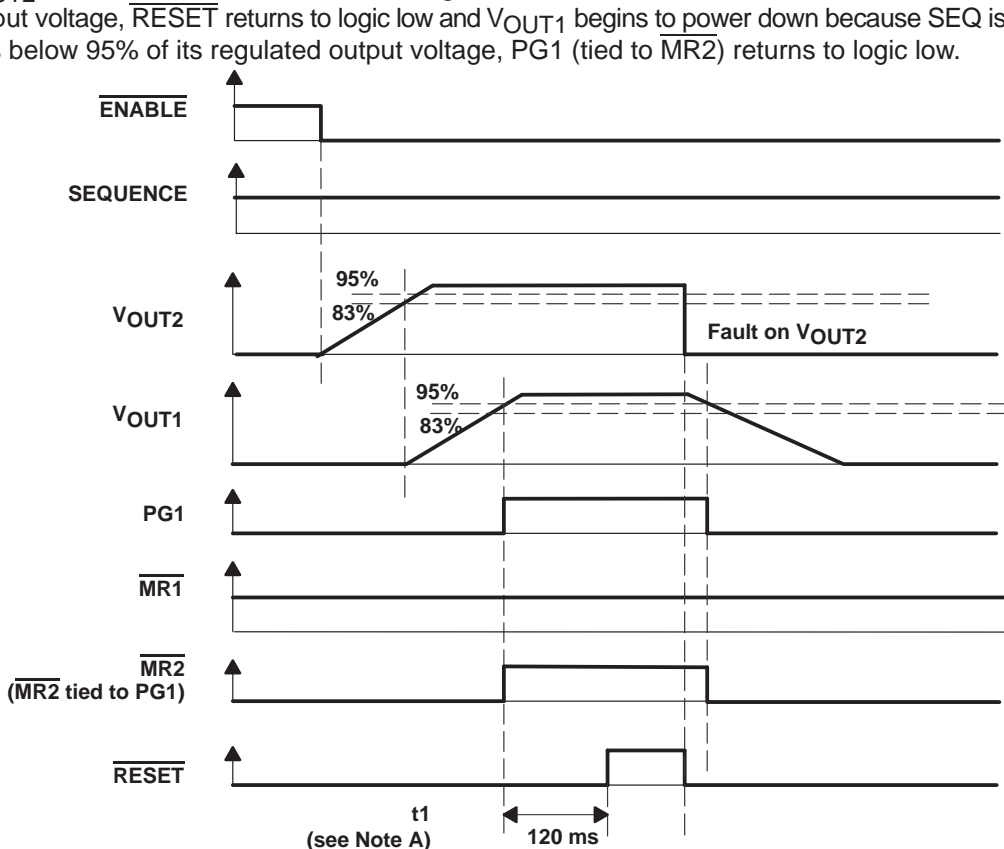
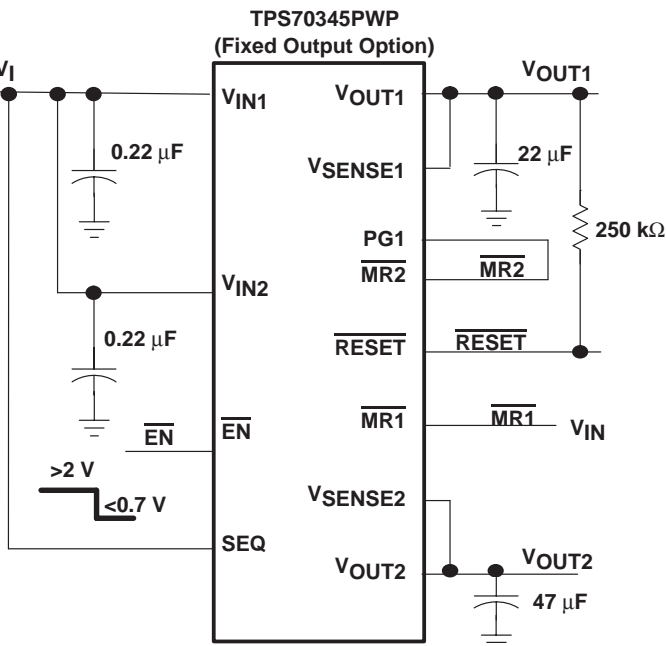
#### sequencing timing diagrams (continued)

application conditions not shown in block diagram:  $V_I$

$V_{IN1}$  and  $V_{IN2}$  are tied to the same fixed input voltage greater than the  $V_{UVLO}$ ; SEQ is tied to logic high; PG1 is tied to MR2; MR1 is not used and is connected to  $V_{IN}$ .

explanation of timing diagrams:

$\overline{EN}$  is initially high; therefore, both regulators are off and PG1 and  $\overline{RESET}$  are at logic low. With SEQ at logic high, when  $\overline{EN}$  is taken low,  $V_{OUT2}$  turns on.  $V_{OUT1}$  turns on after  $V_{OUT2}$  reaches 83% of its regulated output voltage. When  $V_{OUT1}$  reaches 95% of its regulated output voltage, PG1 (tied to MR2) goes to logic high. When both  $V_{OUT1}$  and  $V_{OUT2}$  reach 95% of their respective regulated output voltages and both MR1 and MR2 (tied to PG1) are at logic high,  $\overline{RESET}$  is pulled to logic high after a 120 ms delay. When a fault on  $V_{OUT2}$  causes it to fall below 95% of its regulated output voltage,  $\overline{RESET}$  returns to logic low and  $V_{OUT1}$  begins to power down because SEQ is high. When  $V_{OUT1}$  falls below 95% of its regulated output voltage, PG1 (tied to MR2) returns to logic low.



NOTE A:  $t_1$  – Time at which both  $V_{OUT1}$  and  $V_{OUT2}$  are greater than the PG thresholds and MR1 is logic high.

Figure 30. Timing When a Fault Occurs on  $V_{OUT2}$

# TPS70345-EP

## DUAL-OUTPUT LOW-DROPOUT VOLTAGE REGULATORS

### WITH POWER UP SEQUENCING FOR SPLIT VOLTAGE DSP SYSTEMS

SGLS323A – JANUARY 2006 – REVISED MARCH 2006

#### APPLICATION INFORMATION

##### input capacitor

For a typical application, a ceramic input bypass capacitor (0.22  $\mu\text{F}$  – 1  $\mu\text{F}$ ) is recommended to ensure device stability. This capacitor should be as close as possible to the input pin. Due to the impedance of the input supply, large transient currents causes the input voltage to droop. If this droop causes the input voltage to drop below the UVLO threshold, the device turns off. Therefore, it is recommended that a larger capacitor be placed in parallel with the ceramic bypass capacitor at the regulator's input. The size of this capacitor depends on the output current, response time of the main power supply, and the main power supply's distance to the regulator. At a minimum, the capacitor should be sized to ensure that the input voltage does not drop below the minimum UVLO threshold voltage during normal operating conditions.

##### output capacitor

As with most LDO regulators, the TPS70345 requires an output capacitor connected between each OUT and GND to stabilize the internal control loop. The minimum recommended capacitance value for  $V_{\text{OUT}1}$  is 22  $\mu\text{F}$  and the ESR (equivalent series resistance) must be between 50 m $\Omega$  and 800 m $\Omega$ . The minimum recommended capacitance value for  $V_{\text{OUT}2}$  is 47  $\mu\text{F}$  and the ESR must be between 50 m $\Omega$  and 2  $\Omega$ . Solid tantalum electrolytic, aluminum electrolytic, and multilayer ceramic capacitors are all suitable, provided they meet the requirements described above. Larger capacitors provide a wider range of stability and better load transient response. Below is a partial listing of surface-mount capacitors usable with the TPS70345 for fast transient response application. This information, along with the ESR graphs, is included to assist in selection of suitable capacitance for the user's application. When necessary to achieve low height requirements along with high output current and/or high load capacitance, several higher ESR capacitors can be used in parallel to meet the guidelines above.

VALUE	MFR.	PART NO.
680 $\mu\text{F}$	Kemet	T510X6871004AS
470 $\mu\text{F}$	Sanyo	4TPB470M
150 $\mu\text{F}$	Sanyo	4TPC150M
220 $\mu\text{F}$	Sanyo	2R5TPC220M
100 $\mu\text{F}$	Sanyo	6TPC100M
68 $\mu\text{F}$	Sanyo	10TPC68M
68 $\mu\text{F}$	Kemet	T495D6861006AS
47 $\mu\text{F}$	Kemet	T495D4761010AS
33 $\mu\text{F}$	Kemet	T495C3361016AS
22 $\mu\text{F}$	Kemet	T495C2261010AS

##### regulator protection

Both TPS70345 PMOS-pass transistors have built-in back diodes that conduct reverse currents when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. When extended reverse voltage is anticipated, external limiting may be appropriate.

The TPS70345 also features internal current limiting and thermal protection. During normal operation, the TPS70345 regulator 1 limits output current to approximately 1.75 A (typ) and regulator 2 limits output current to approximately 3.8 A (typ). When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds 150°C(yp), thermal-protection circuitry shuts it down. Once the device has cooled below 130°C(yp), regulator operation resumes.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">TPS70345MPWPREP</a>	Active	Production	HTSSOP (PWP)   24	2000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-55 to 125	T70345MEP
TPS70345MPWPREP.A	Active	Production	HTSSOP (PWP)   24	2000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-55 to 125	T70345MEP
<a href="#">V62/06616-01XE</a>	Active	Production	HTSSOP (PWP)   24	2000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-55 to 125	T70345MEP

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

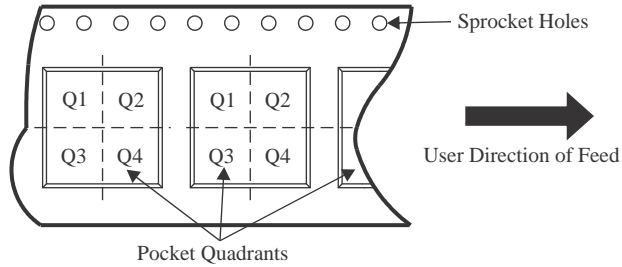
(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS70345MPWPREP	HTSSOP	PWP	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS70345MPWPREP	HTSSOP	PWP	24	2000	350.0	350.0	43.0

## GENERIC PACKAGE VIEW

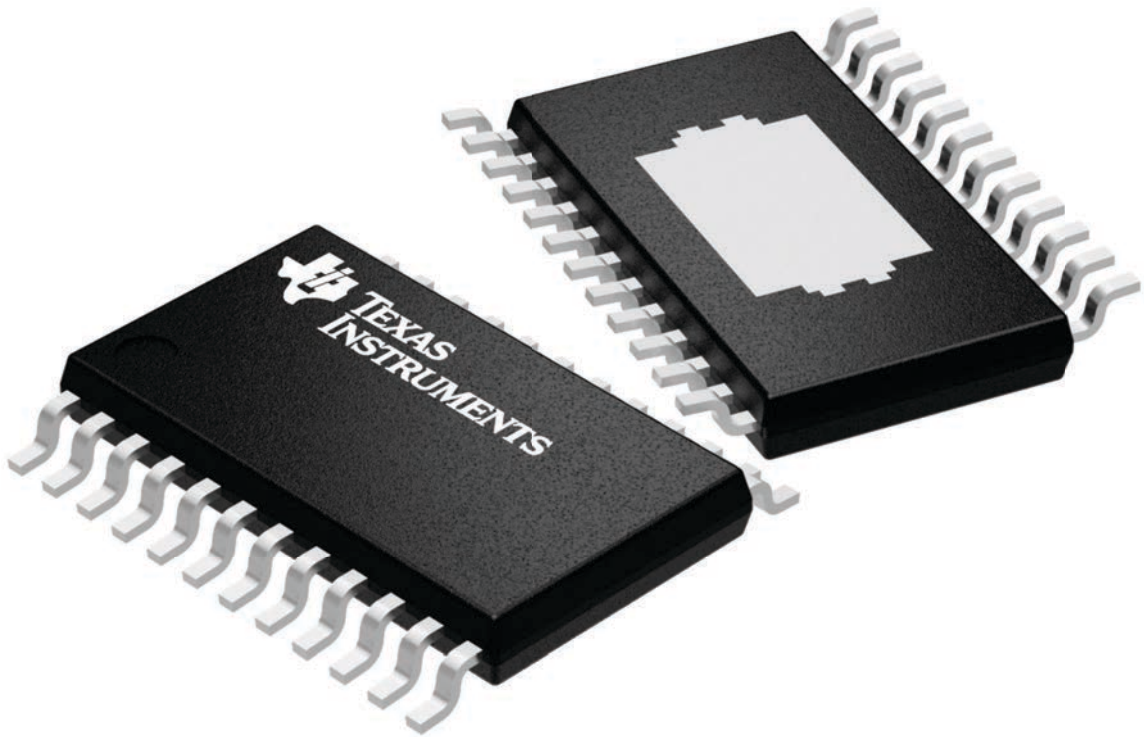
**PWP 24**

**PowerPAD™ TSSOP - 1.2 mm max height**

4.4 x 7.6, 0.65 mm pitch

PLASTIC SMALL OUTLINE

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

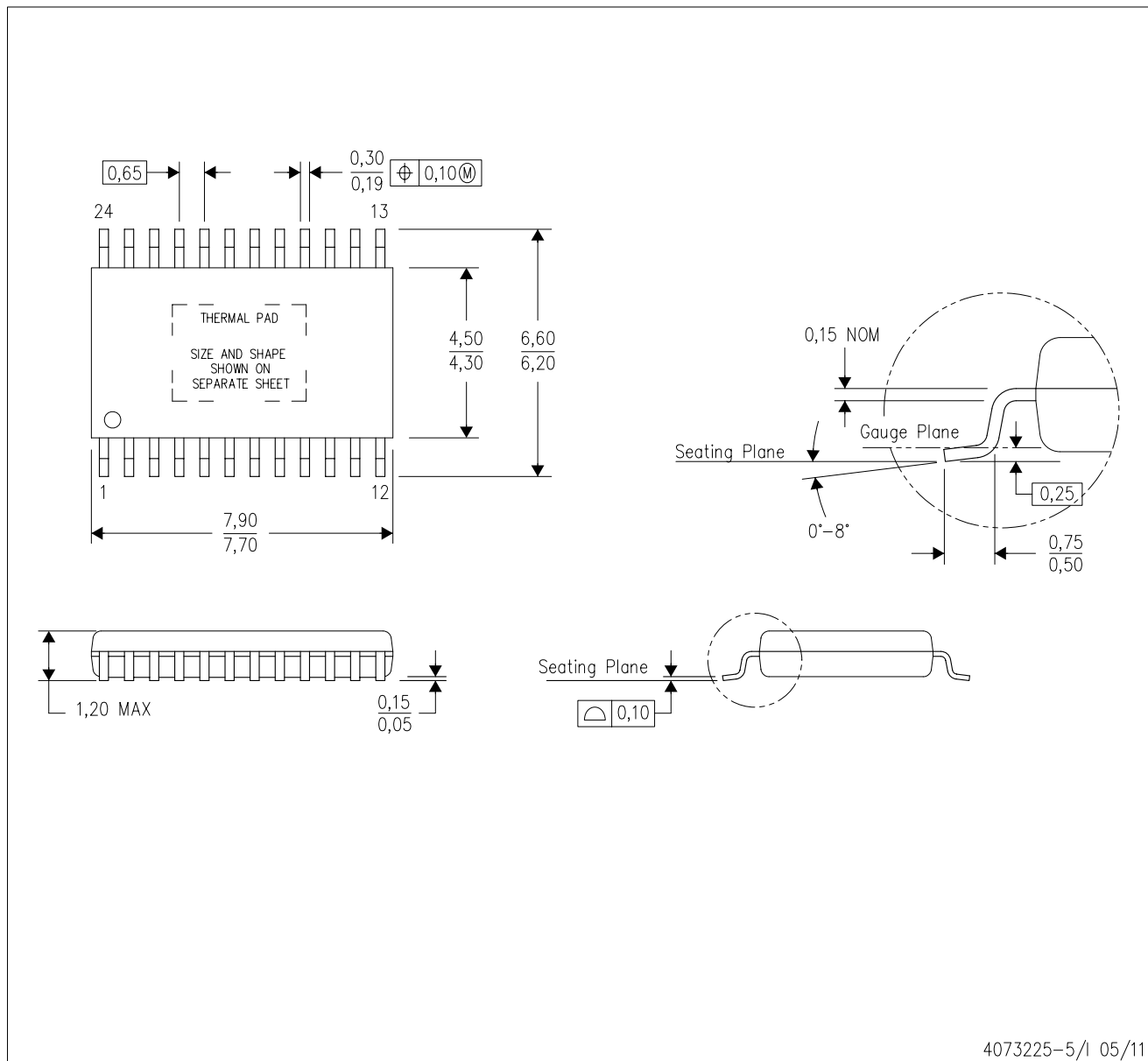


4224742/B

# MECHANICAL DATA

PWP (R-PDSO-G24)

PowerPAD™ PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusions. Mold flash and protrusion shall not exceed 0.15 per side.
  - This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
  - See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
  - Falls within JEDEC MO-153

PowerPAD is a trademark of Texas Instruments.

# THERMAL PAD MECHANICAL DATA

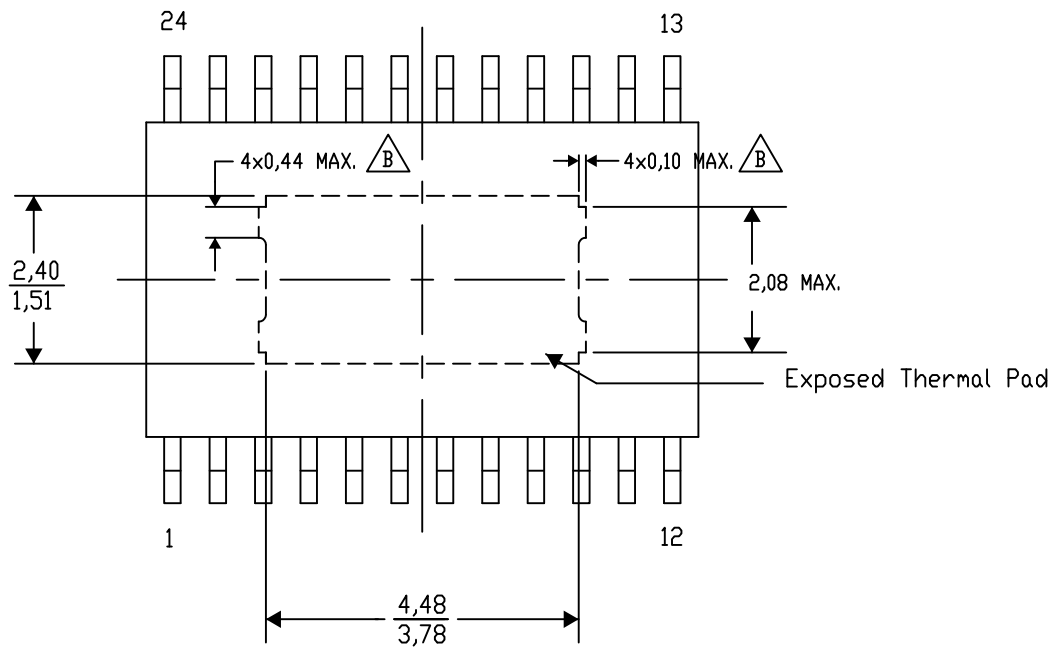
## PWP (R-PDSO-G24) PowerPAD™ SMALL PLASTIC OUTLINE

### THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.




Top View

Exposed Thermal Pad Dimensions

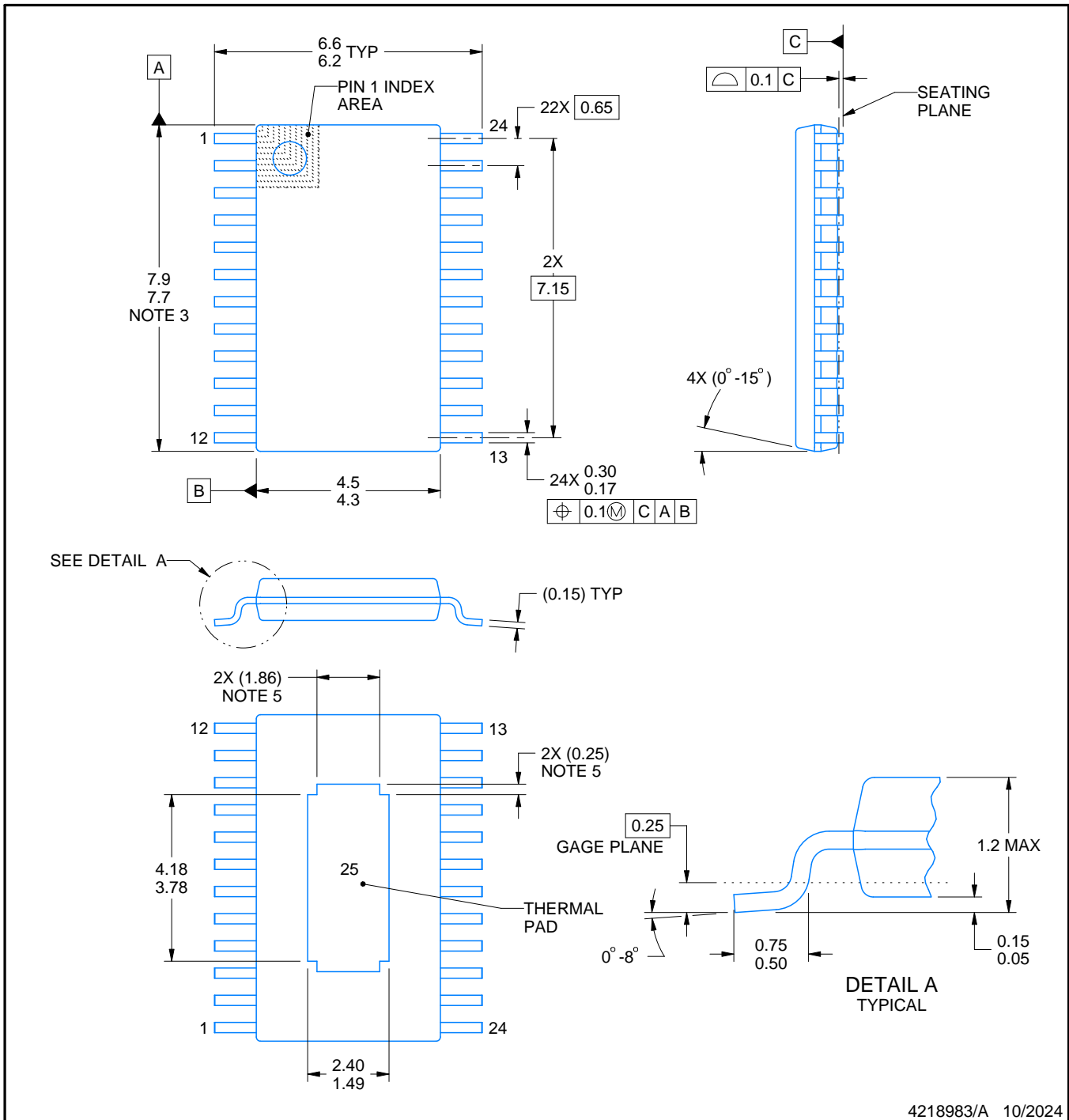
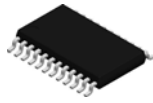
4206332-42/AO 01/16

NOTE: A. All linear dimensions are in millimeters

 B. Exposed tie strap features may not be present.

PowerPAD is a trademark of Texas Instruments





4218983/A 10/2024

NOTES:

PowerPAD is a trademark of Texas Instruments.

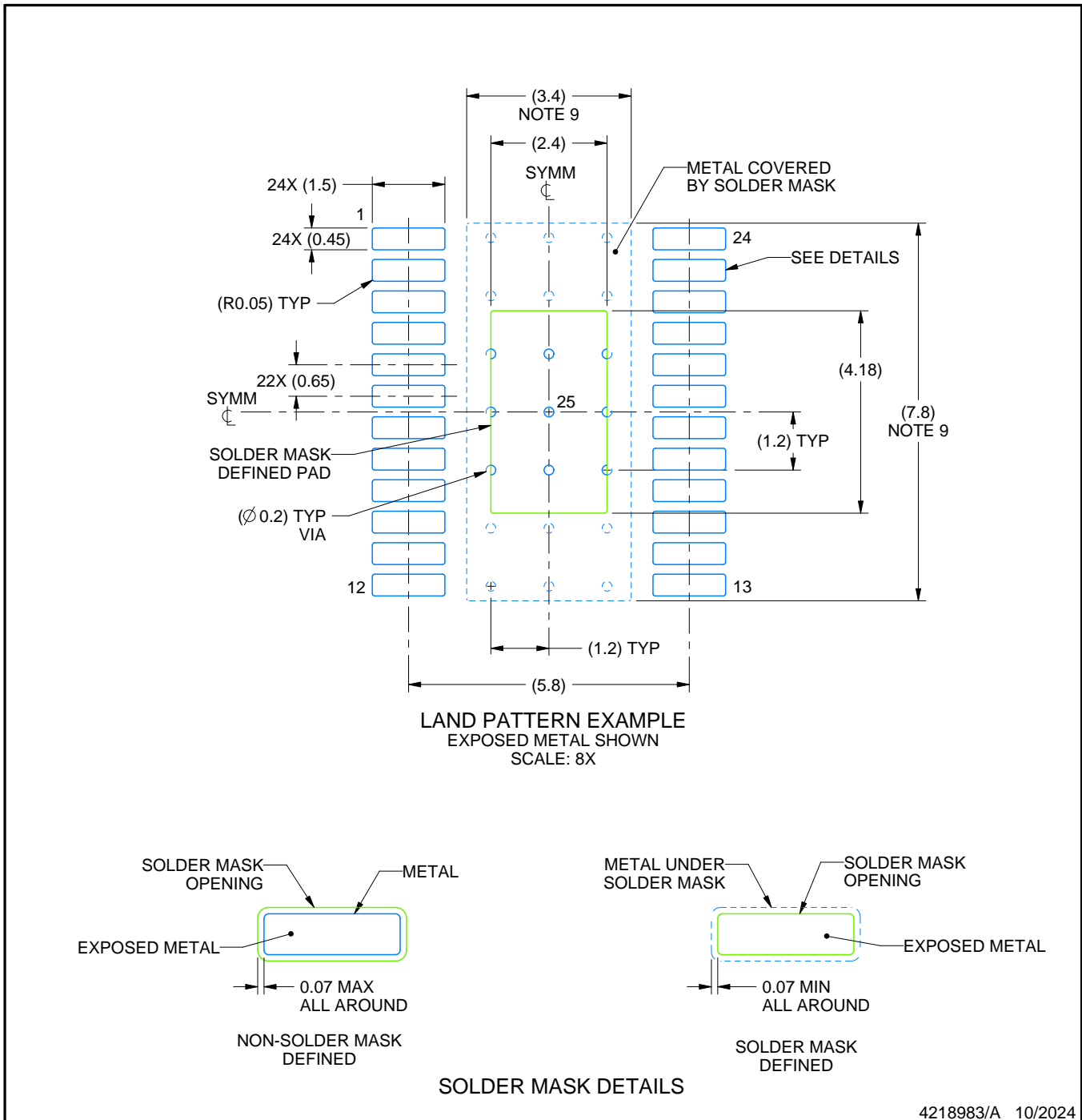
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.
5. Features may differ or may not be present.

# EXAMPLE BOARD LAYOUT

PWP0024A

PowerPAD™ TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4218983/A 10/2024

NOTES: (continued)

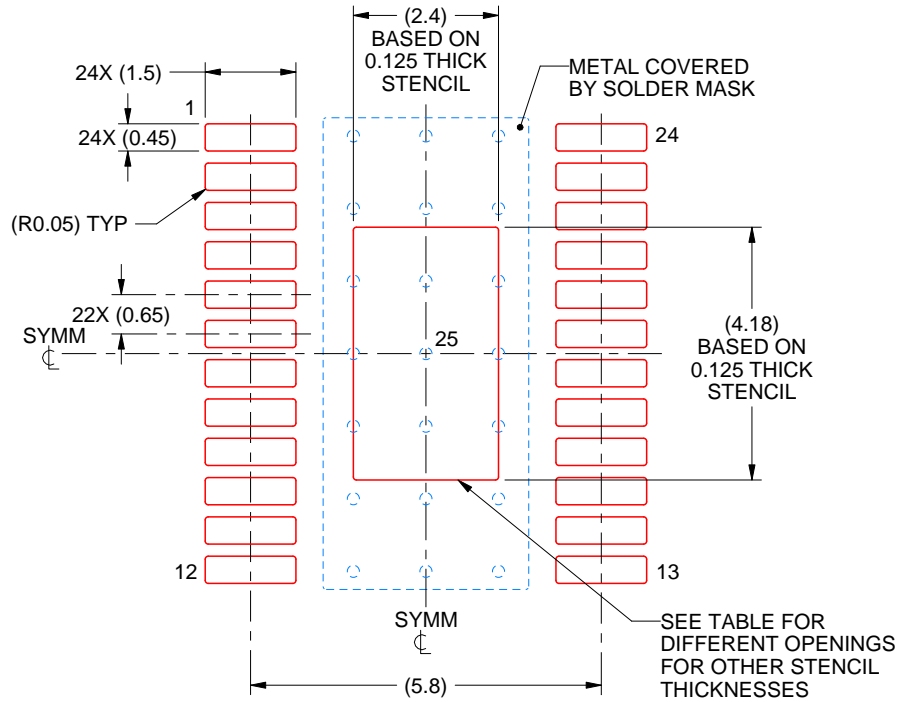
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 ([www.ti.com/lit/slma002](http://www.ti.com/lit/slma002)) and SLMA004 ([www.ti.com/lit/slma004](http://www.ti.com/lit/slma004)).
9. Size of metal pad may vary due to creepage requirement.
10. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

PWP0024A

PowerPAD™ TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
 BASED ON 0.125 mm THICK STENCIL  
 SCALE: 8X

STENCIL THICKNESS	SOLDER STENCIL OPENING
0.1	2.68 X 4.67
0.125	2.40 X 4.18 (SHOWN)
0.15	2.19 X 3.82
0.175	2.03 X 3.53

4218983/A 10/2024

NOTES: (continued)

- 11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 12. Board assembly site may have different recommendations for stencil design.

## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#), [TI's General Quality Guidelines](#), or other applicable terms available either on [ti.com](#) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025